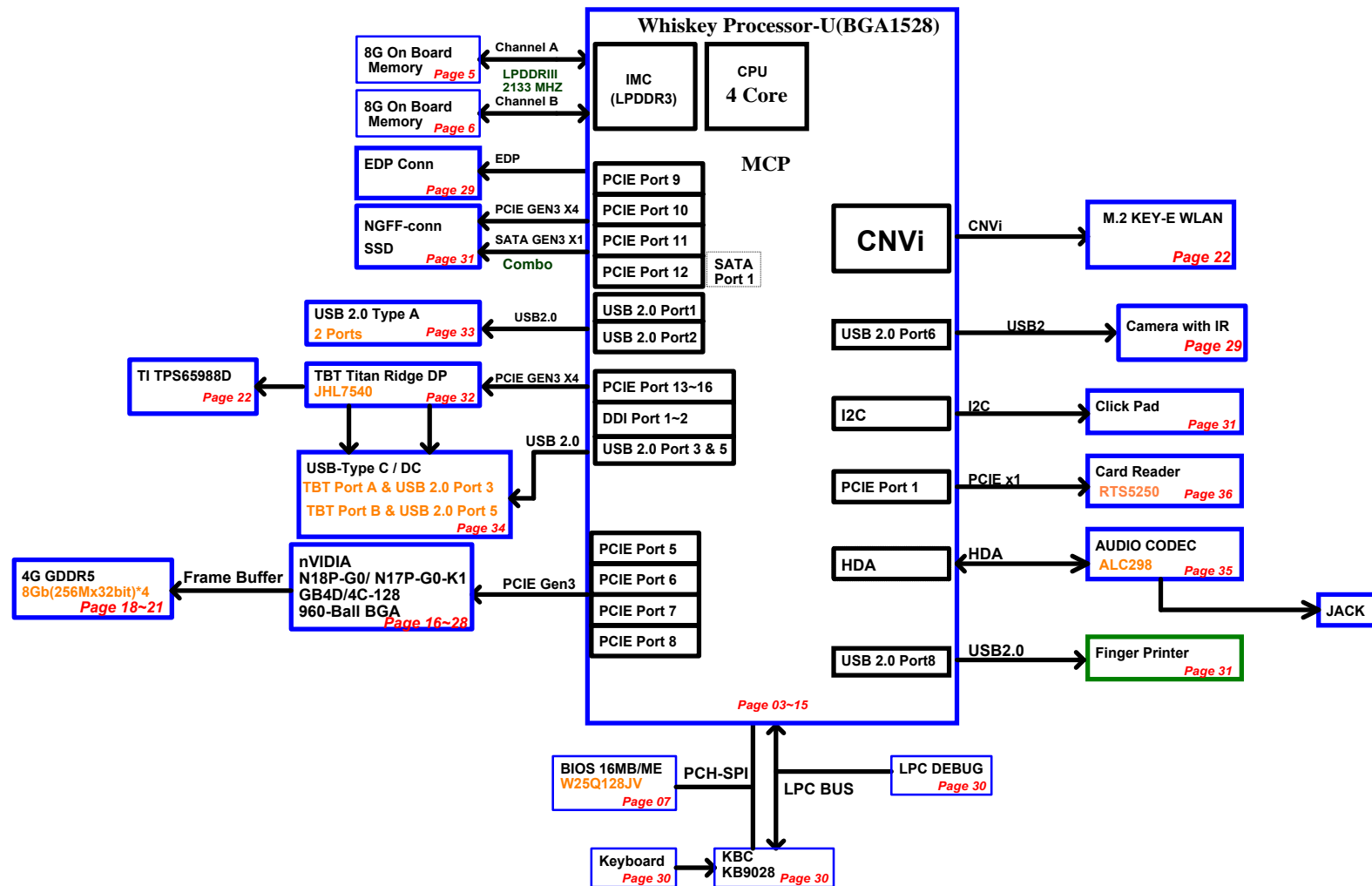


Whiskey Lake Processor-U Platform MS-14C1 VER : A



SCHEMATIC ANNOTATIONS AND BOARD INFORMATION

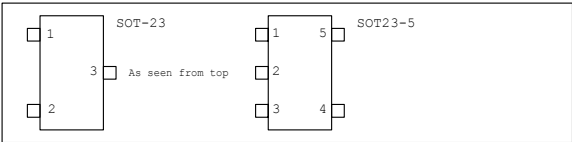
Voltage Rails

Voltage	Description	Control Signal
PWR_SRC	AC ADAPTER OR BATTERY IN	
+5VALW	5.0V always on power rail	PWR_SRC
+3VALW	3.3V always on power rail	PWR_SRC
+5VSUS	5.0V power rail	SUS_ON
+3VSUS	3.3V power rail	SUS_ON
+1_05VSUS	1.0V power rail	+1_8VSUSPWROK
+1_8VSUS	1.8V power rail	3V5VPWROK
+1_2VDIMM/+1_8VDIMM	1.2V power rail DDR (off in S4-S5)	S4_DIMM_ON_AND
+VDDQ_CPU	1.2V power rail CPU DRAM (off in S4-S5)	S4_DIMM_ON_AND
+VCCST/+VCCPLL	1.0V power rail CPU (off in S4-S5)	+1_2VDIMM_PWRGD
+VCCSTG	1.0V power rail CPU (off in S3-S5)	RUND
+5VRUN	5.0V switched power rail (off in S3-S5)	RUND
+3VRUN	3.3V switched power rail (off in S3-S5 / M0)	RUND
+0_6VRUN	0.6V DDR Termination voltage (off in S3-S5)	DDR_VTT_CTRL
+1_8VRUN	1.8V power rail AUDIO (off in S3-S5)	RUND
+VCC_IO	1.0V rail for Processor & PCH (off in S3-S5)	RUND
+VCC_SA	0.55V to 1.15V Voltage for Processor	VR_ON
+VCC_GT	0.55V to 1.52V Core Voltage for Processor	VR_ON
+VCC_CORE	0.55V to 1.5V Voltage for Processor	VR_ON

Net Naming Conventions

Suffix
= Active Low Signal
Prefix
H = Host
M = DDR Memory
TP = Test Point (does not connect anywhere else)

PCB Footprints



POWER STATES

STATE \ SIGNAL	SLP_S3#	SLP_S4#	SLP_S5#	+V*ALWAYS	+3VSUS	+*VSUS	+*VRUN	+VTT_CORE	Clocks
S0(Full ON)	HIGH	HIGH	HIGH	ON	ON	ON	ON	ON	ON
S3(Suspend to RAM)	LOW	HIGH	HIGH	ON	ON	ON	OFF	OFF	OFF
S4(Suspend to Disk)	LOW	LOW	HIGH	ON	OFF	OFF	OFF	OFF	OFF
S5 (Soft OFF)	LOW	LOW	LOW	ON	OFF	OFF	OFF	OFF	OFF
S3(Suspend to RAM) WOL_EN	LOW	HIGH	HIGH	ON	ON	ON	OFF	OFF	OFF
S4(Suspend to Disk) WOL_EN	LOW	LOW	HIGH	ON	ON	ON	OFF	OFF	OFF
S5 (Soft OFF) WOL_EN	LOW	LOW	LOW	ON	ON	ON	OFF	OFF	OFF

Note : WHEN AC MODE , System turn on then +V*SUS will always keep high

MICRO-STAR INT'L CO.,LTD.

Title

PLATFORM

Size

Custom

Document Number

MS-14C1

Date:

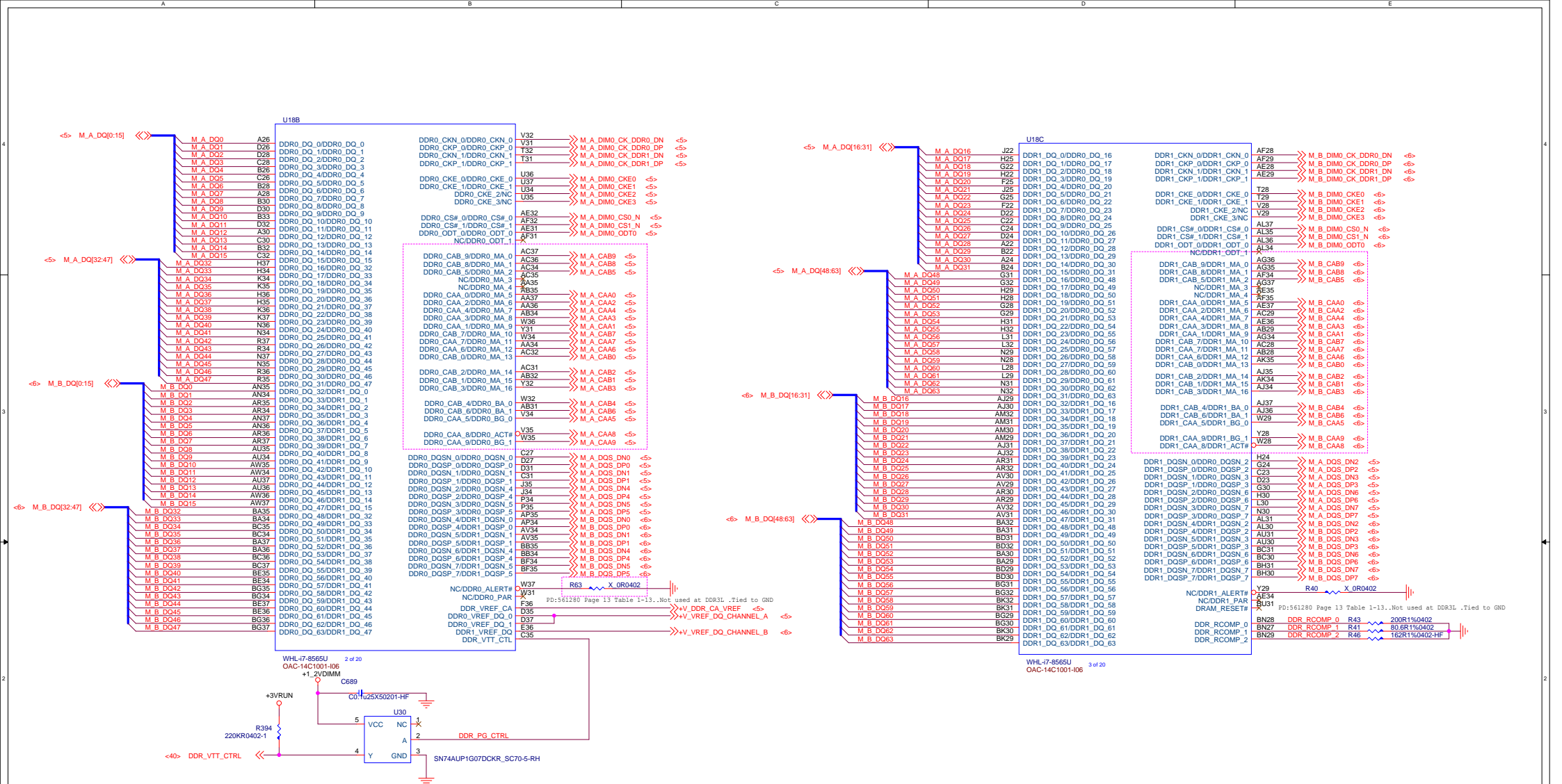
Friday, April 12, 2019

Rev

0A

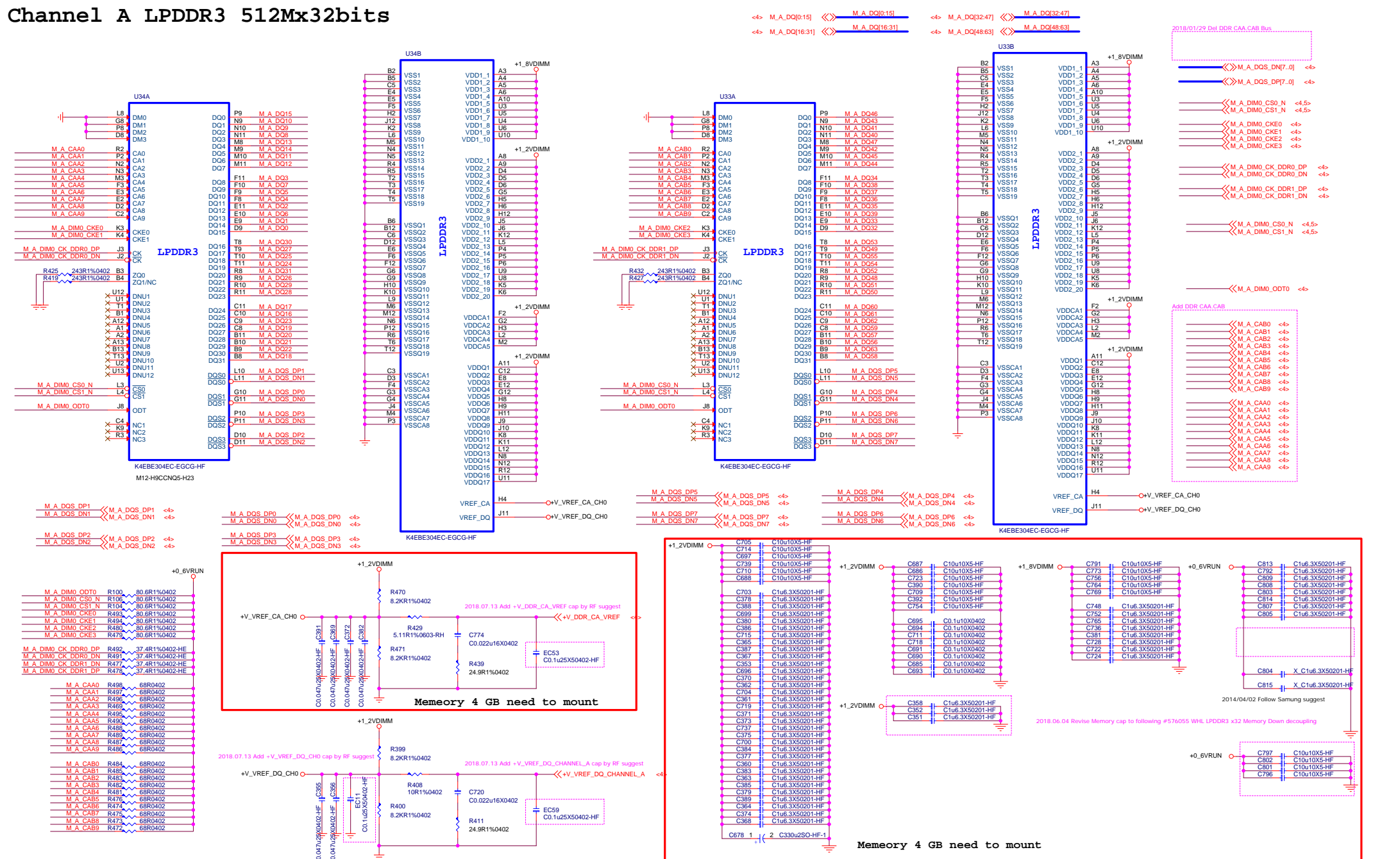
Sheet

2 of 56

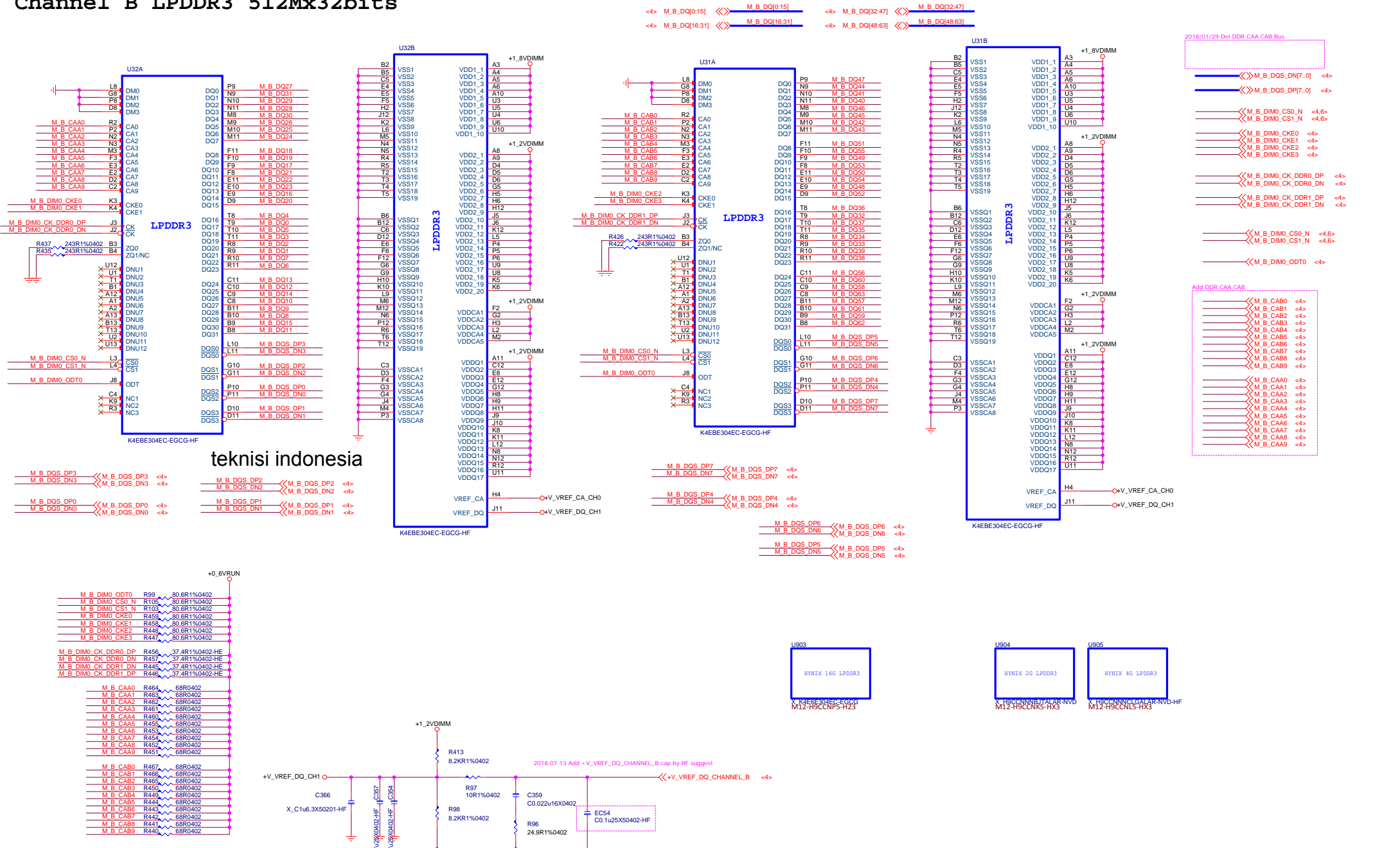


Vinafix.com

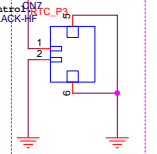
Channel A LPDDR3 512Mx32bits

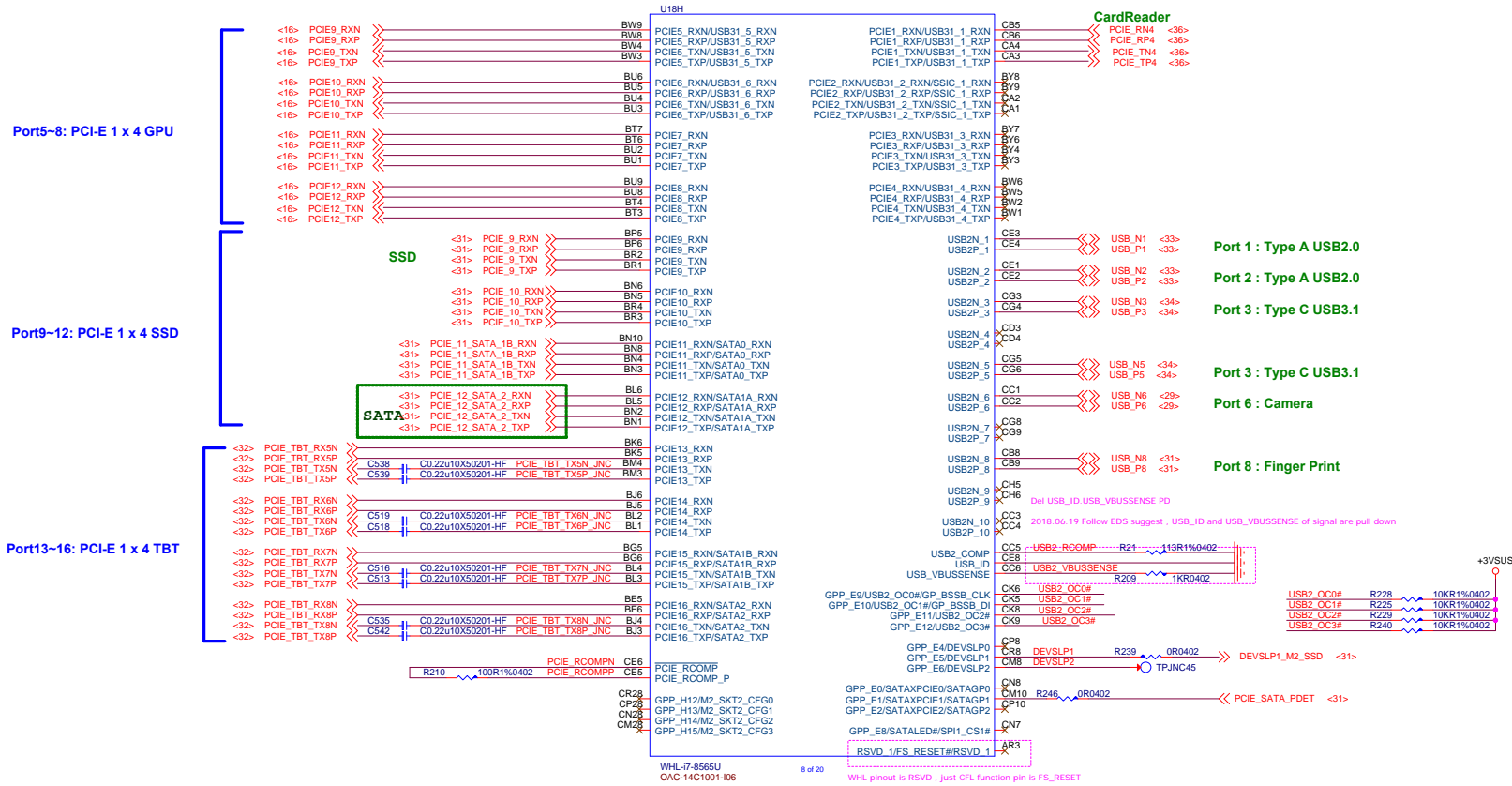


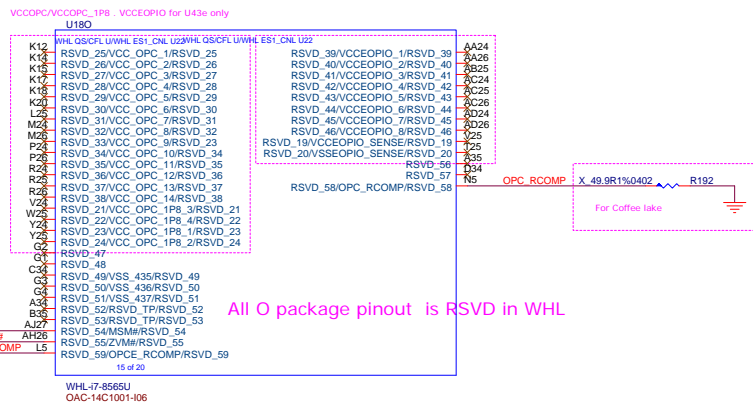
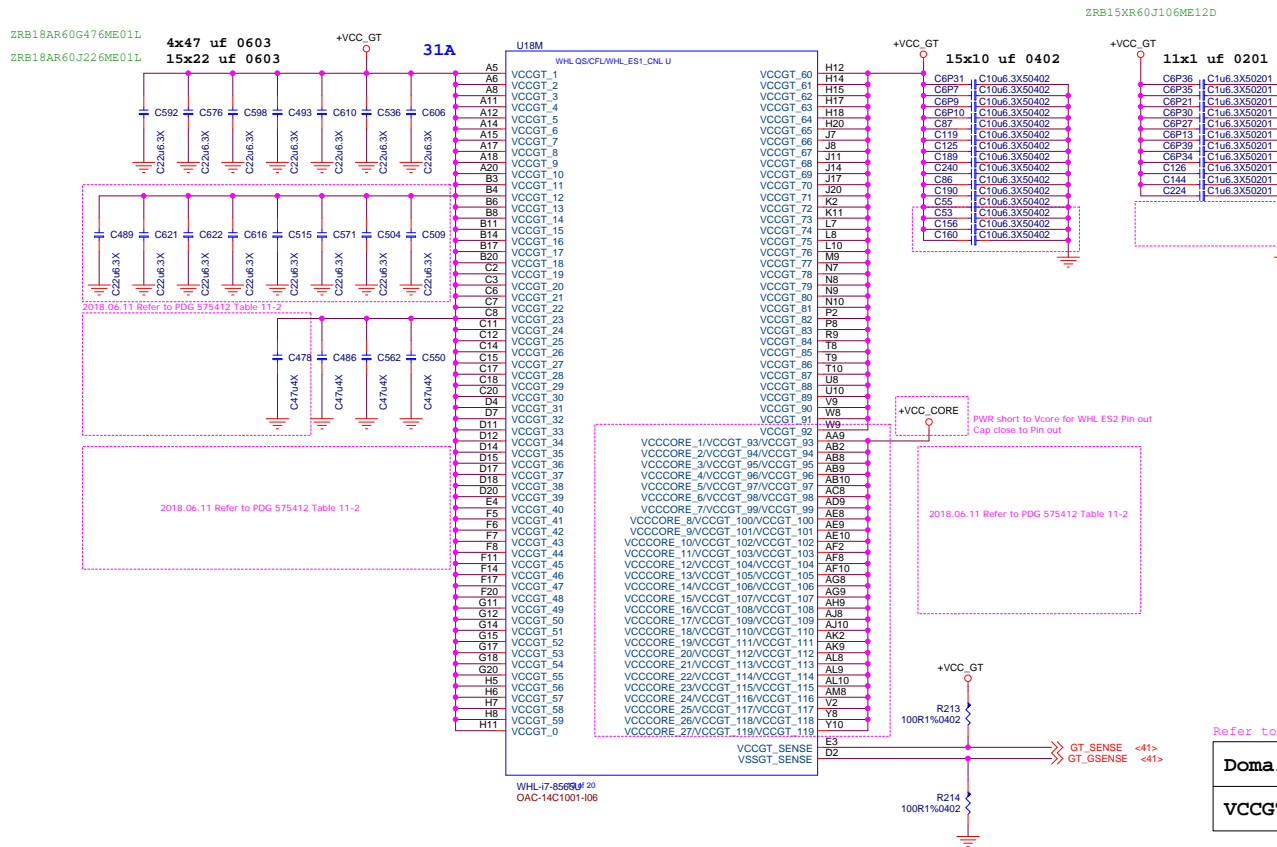
Channel B LPDDR3 512Mx32bits



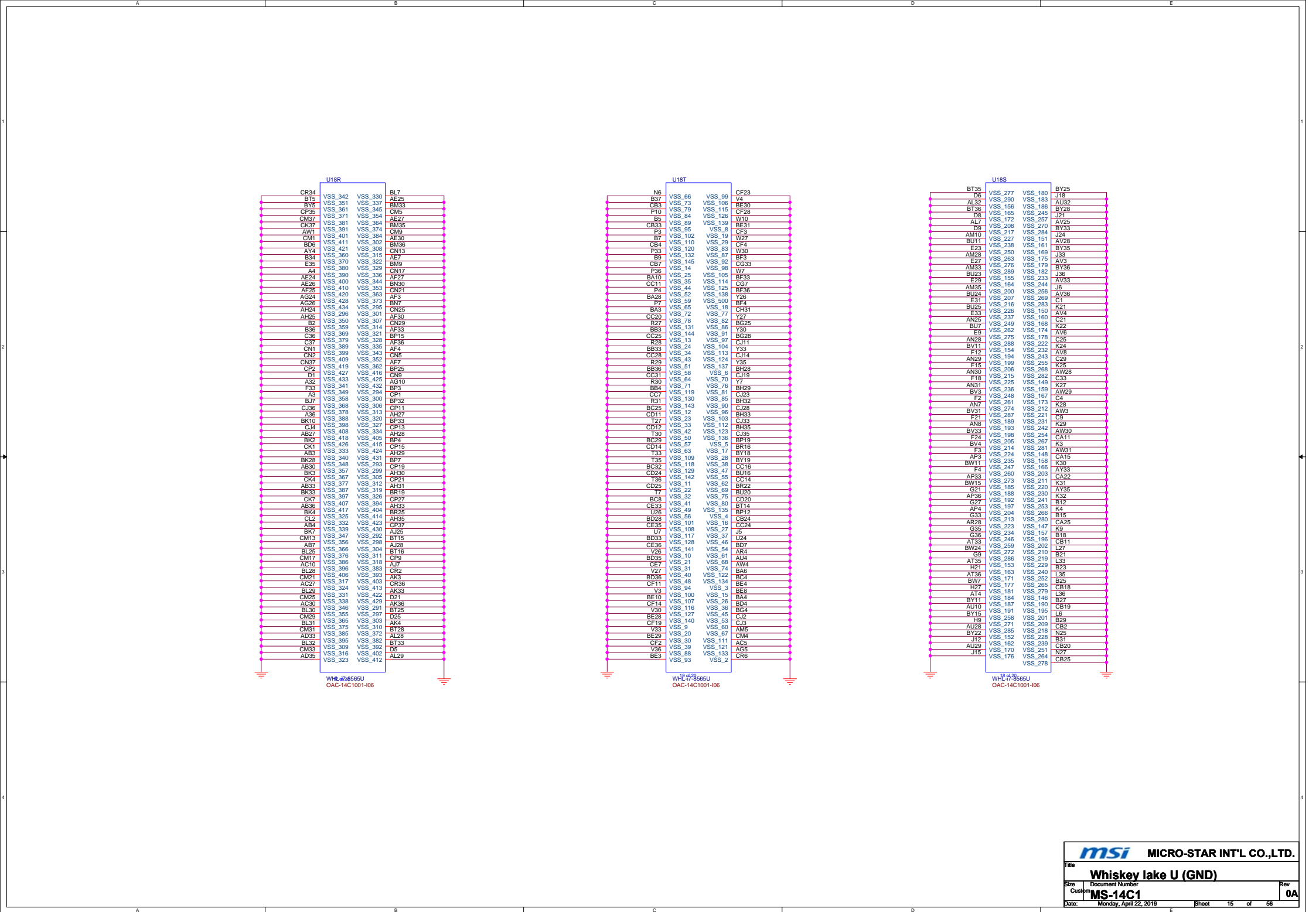
tekni indonesia



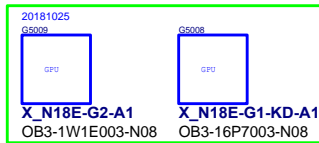




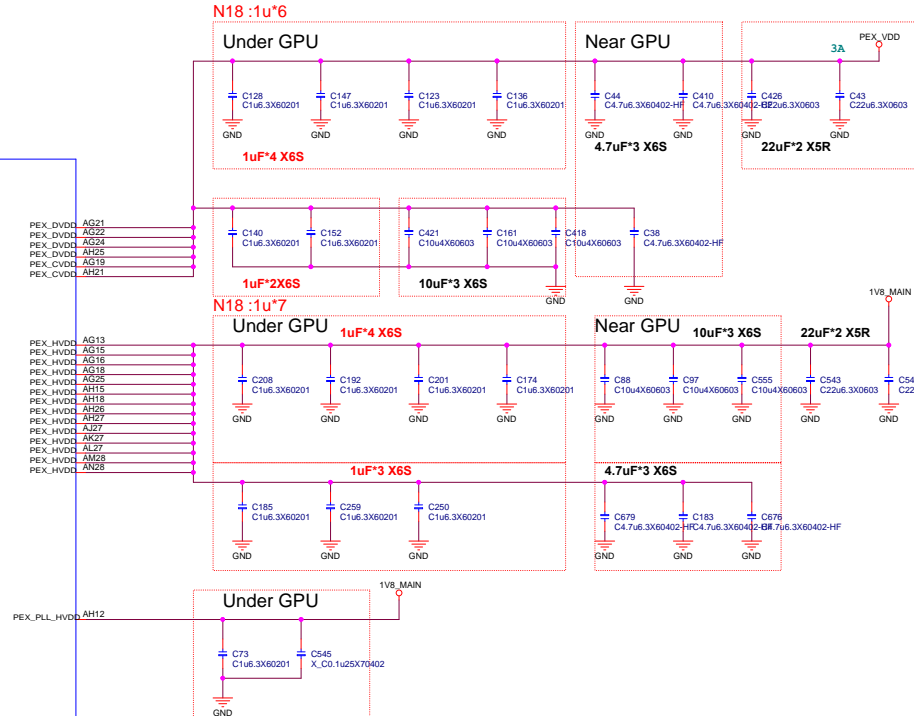
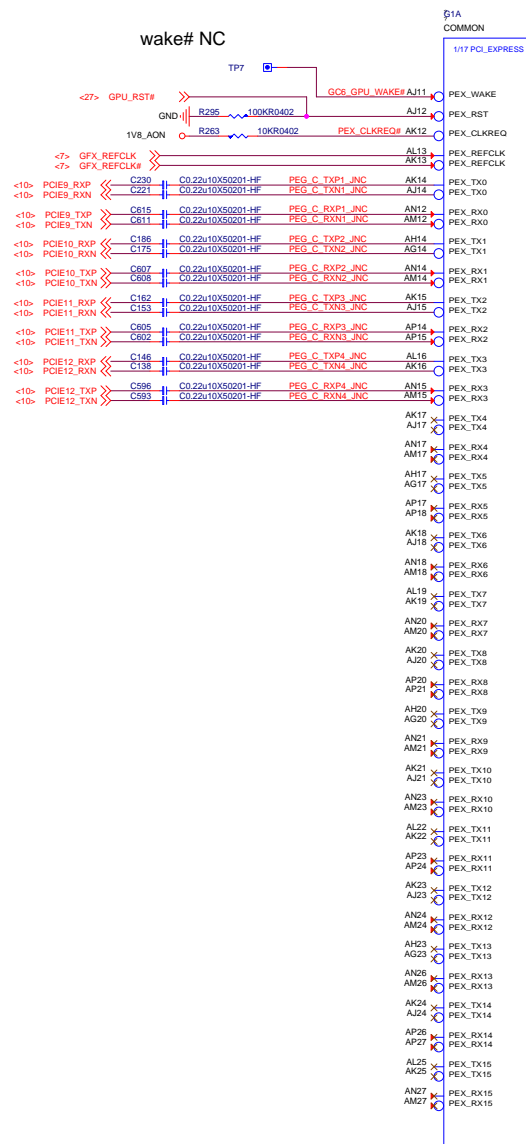
All O package pinout is RSVD in WHL



GPU PCI EXPRESS

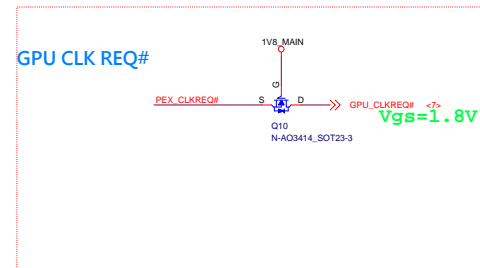


N18:0.47u*15,change 10,4.7u*3,10u*3,22u*2
N17:1u*4,4.7u*2,10u,22u*1

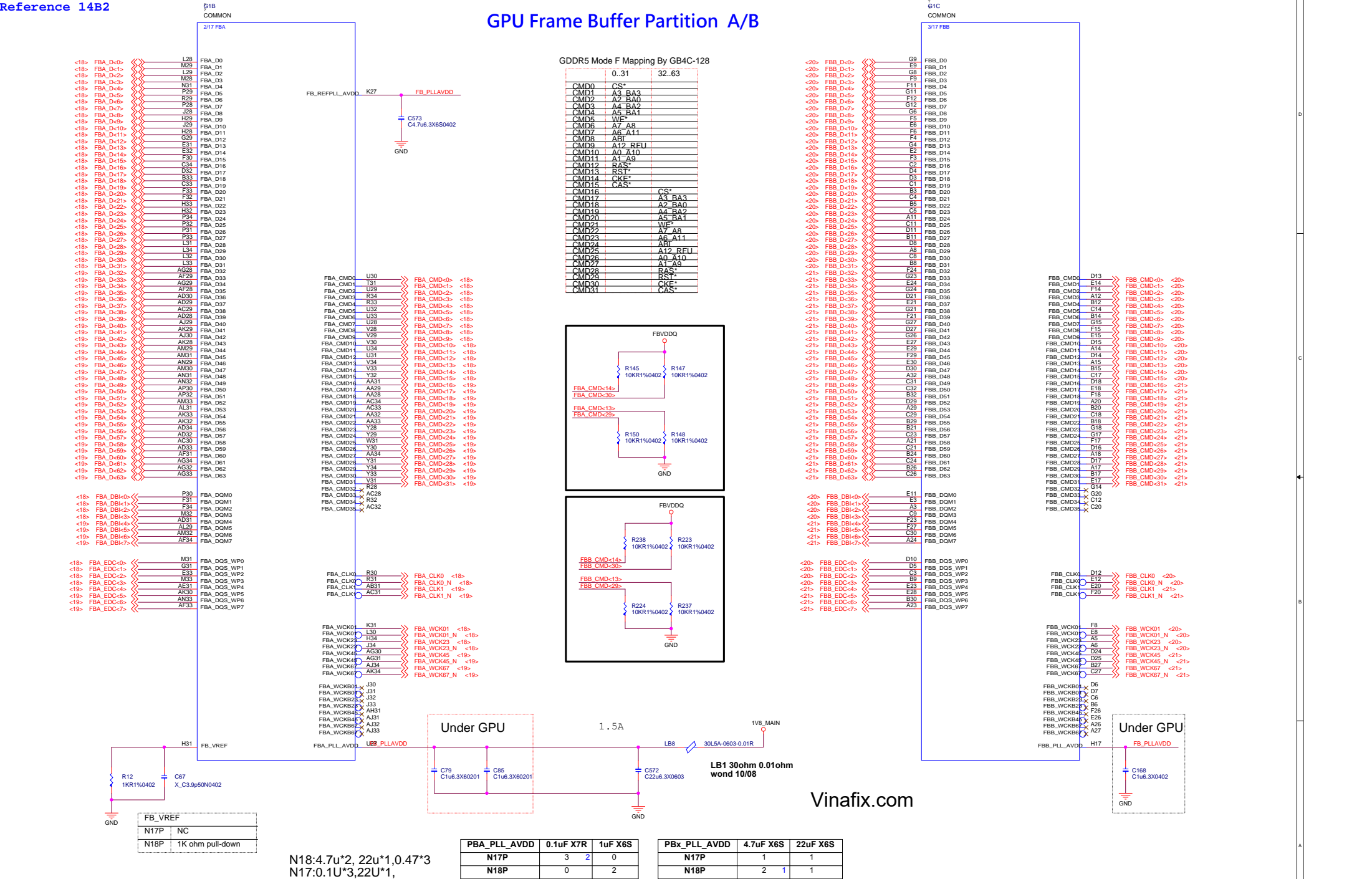


PEX_DVDD	1uF X6S	4.7uF X6S	10uF X6S	22uF X5R
N17P	4	2	1	1
N18P	6	3	3	2

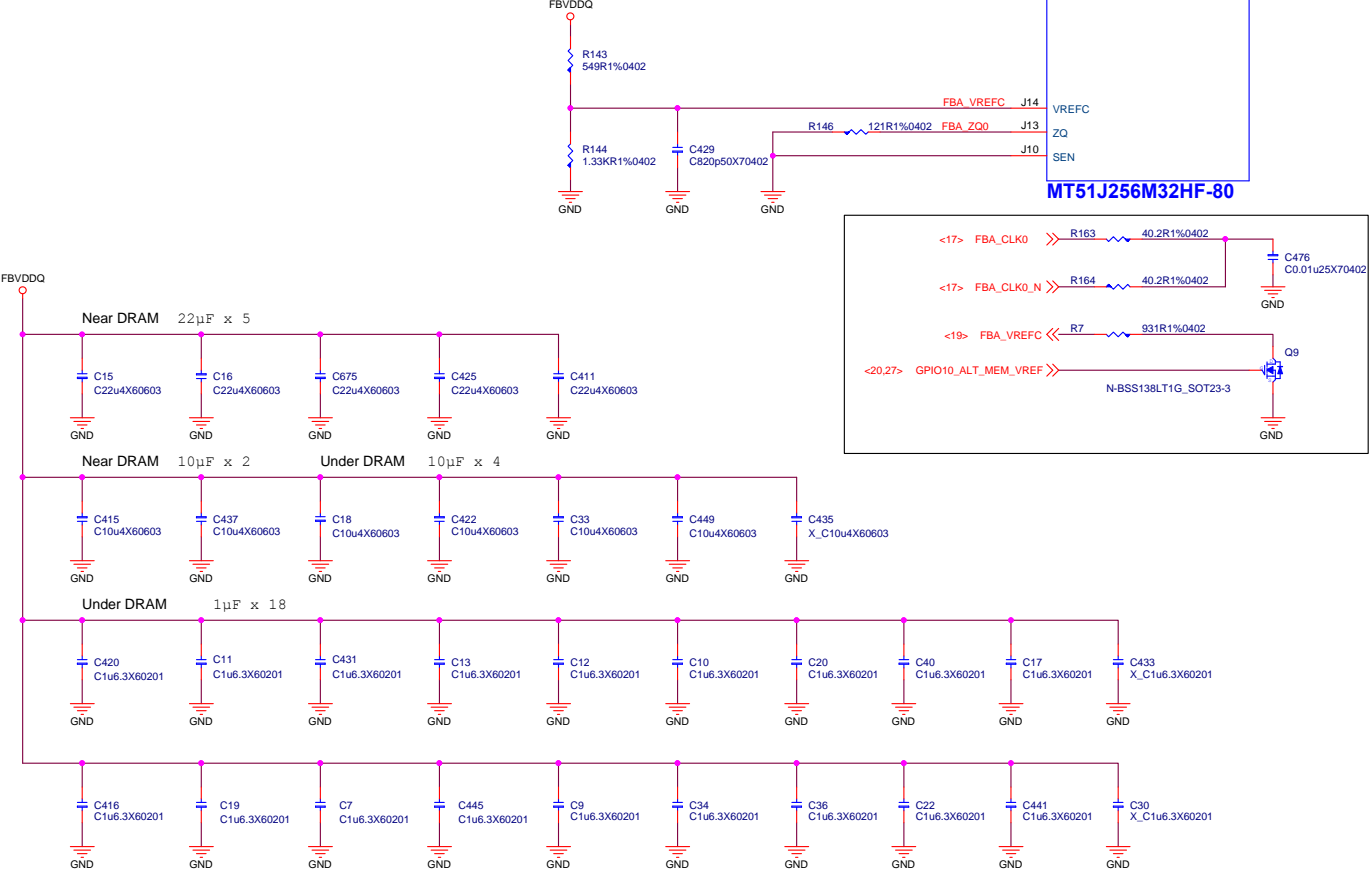
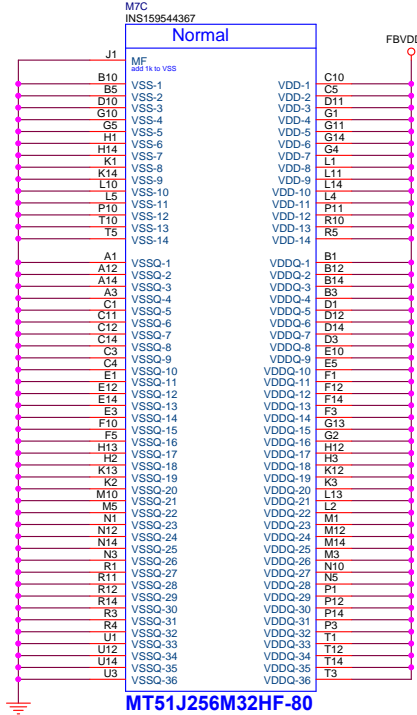
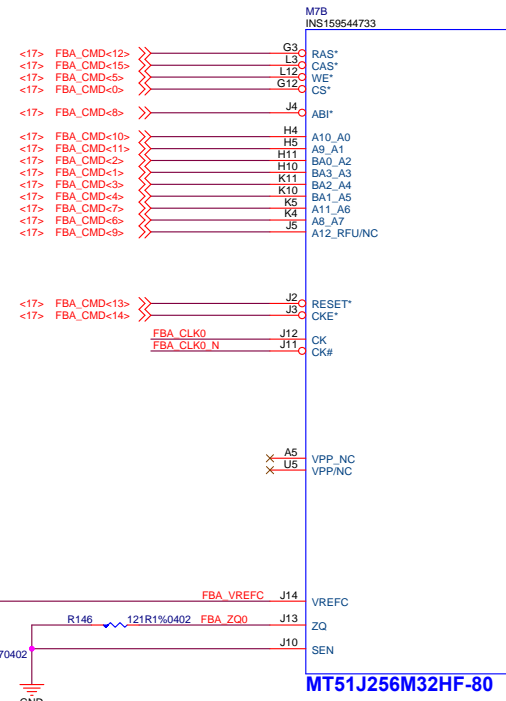
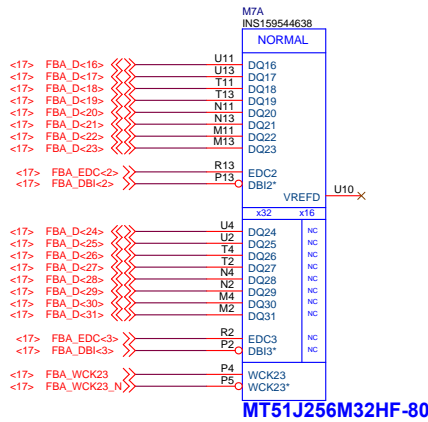
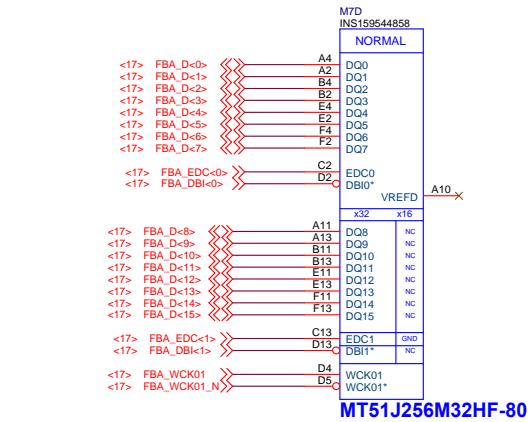
PEX _{min} HVDD	1uF X6S	4.7uF X6S	10uF X6S	22uF X5R
N17P	4	2	2	1
N18P	7	3	3	2



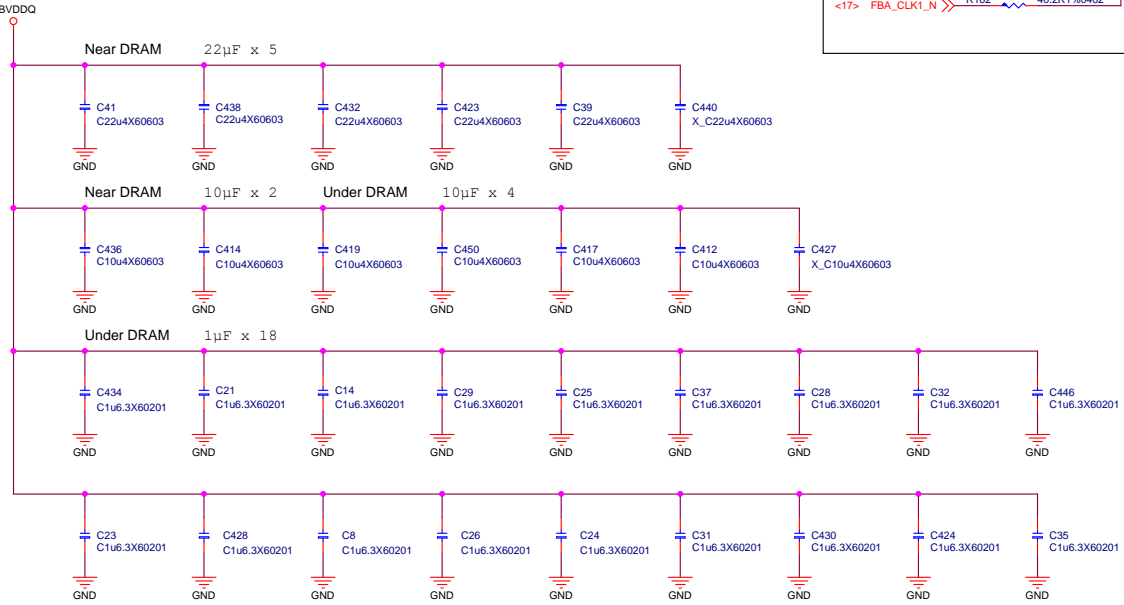
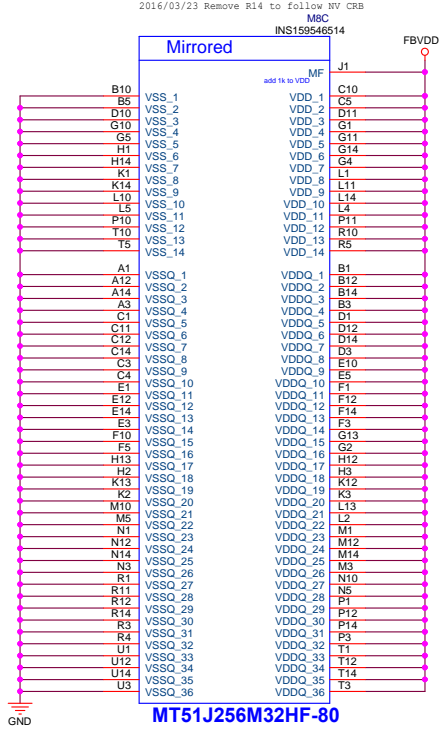
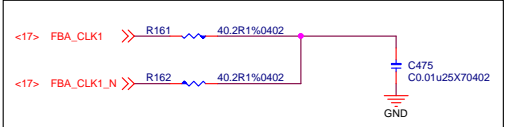
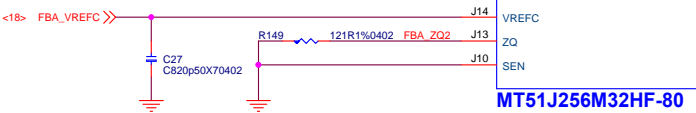
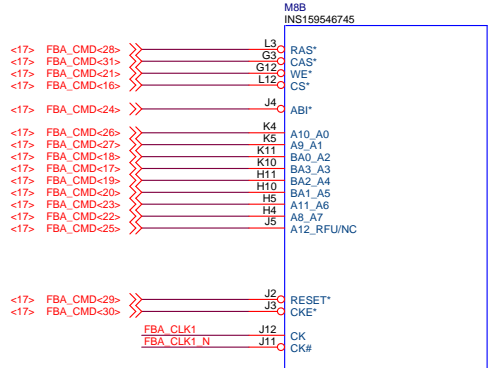
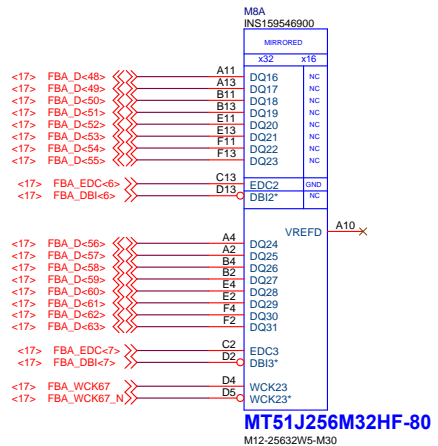
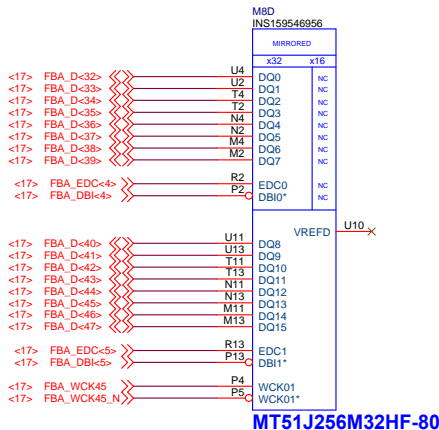
GPU Frame Buffer Partition A/B



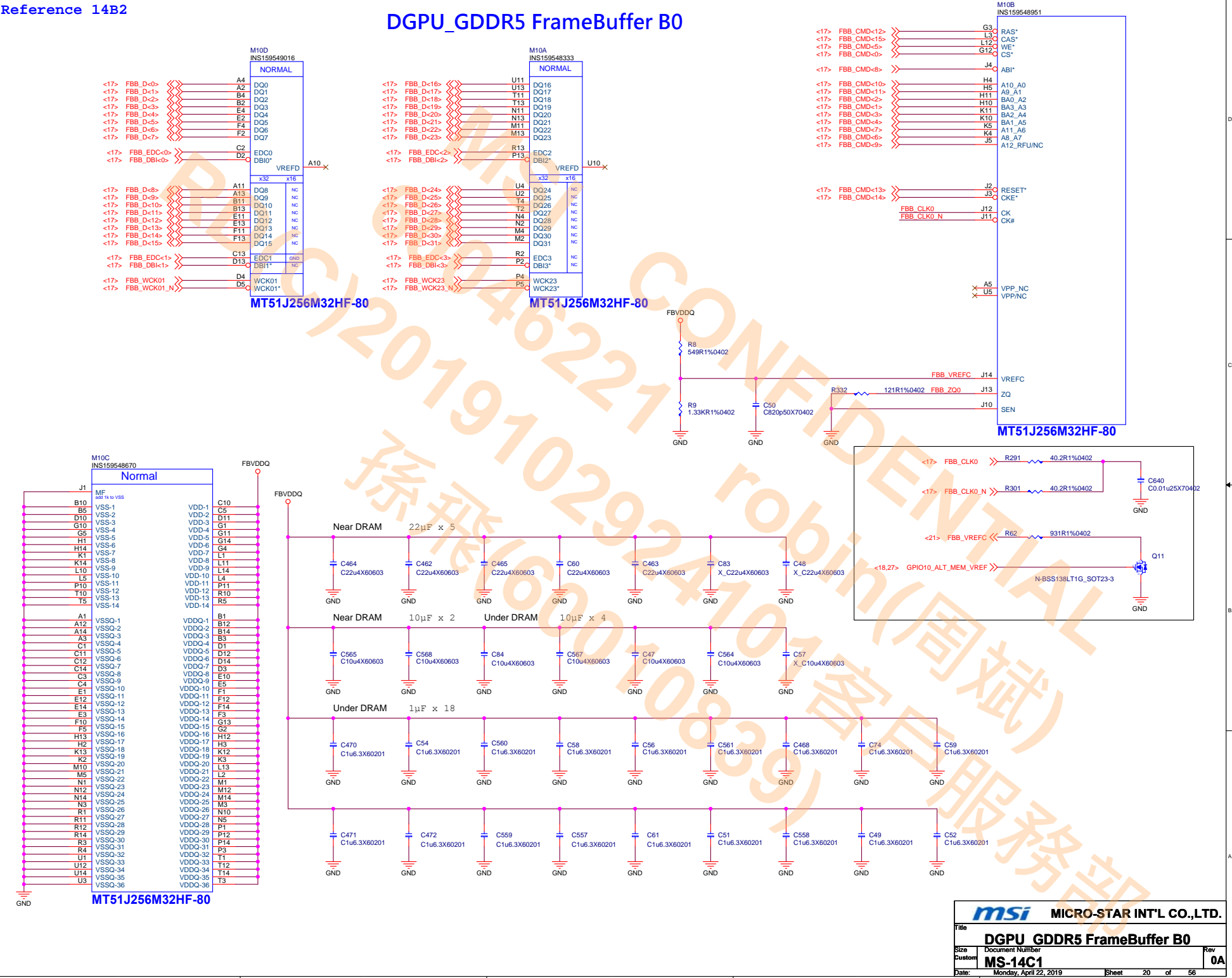
DGPU_GDDR5 FrameBuffer A0

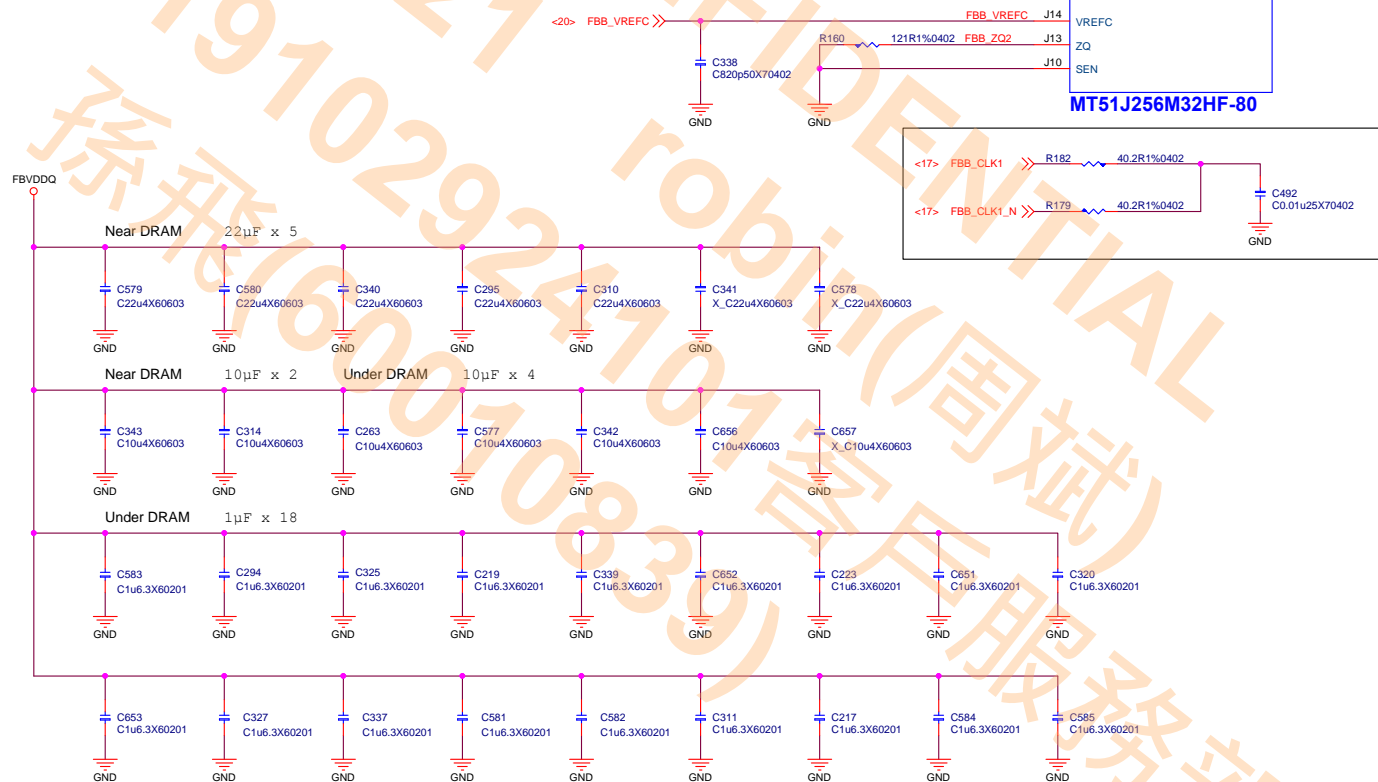
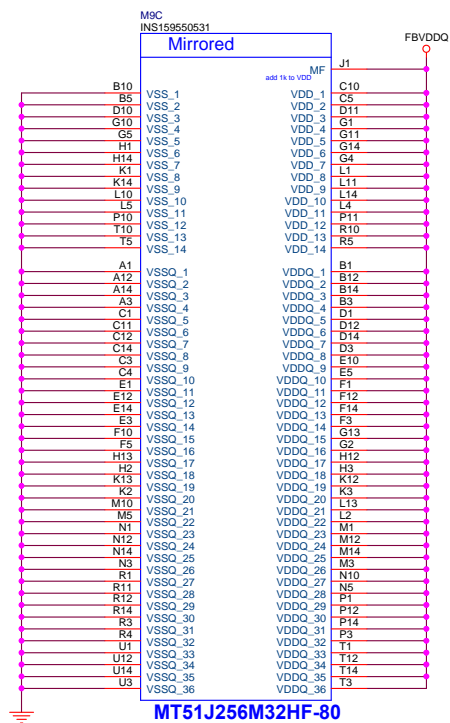
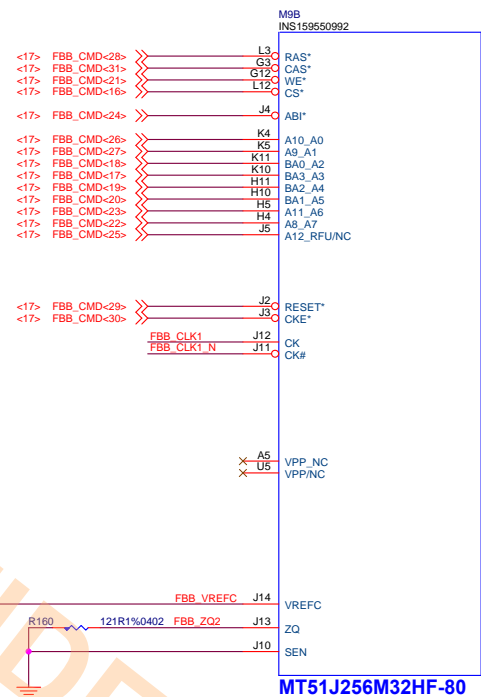
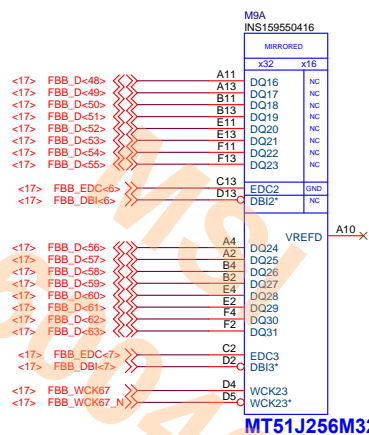


DGPU_GDDR5 FrameBuffer A1

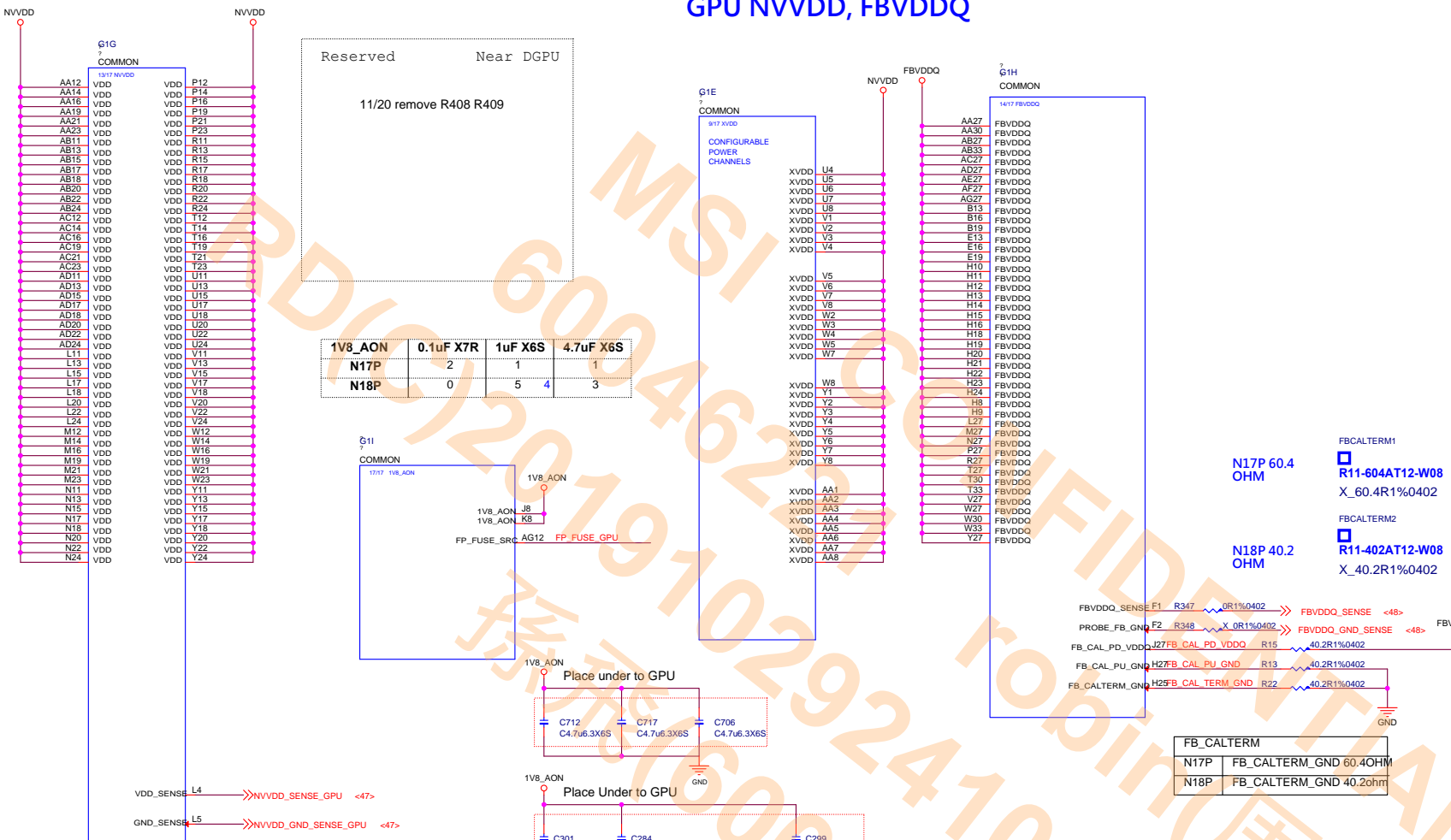


DGPU_GDDR5 FrameBuffer B0

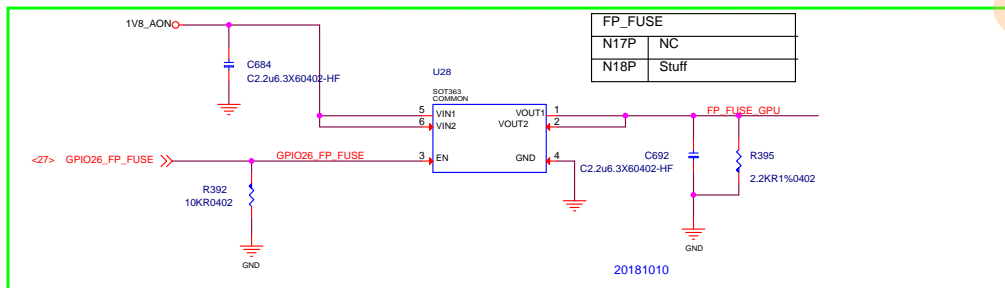




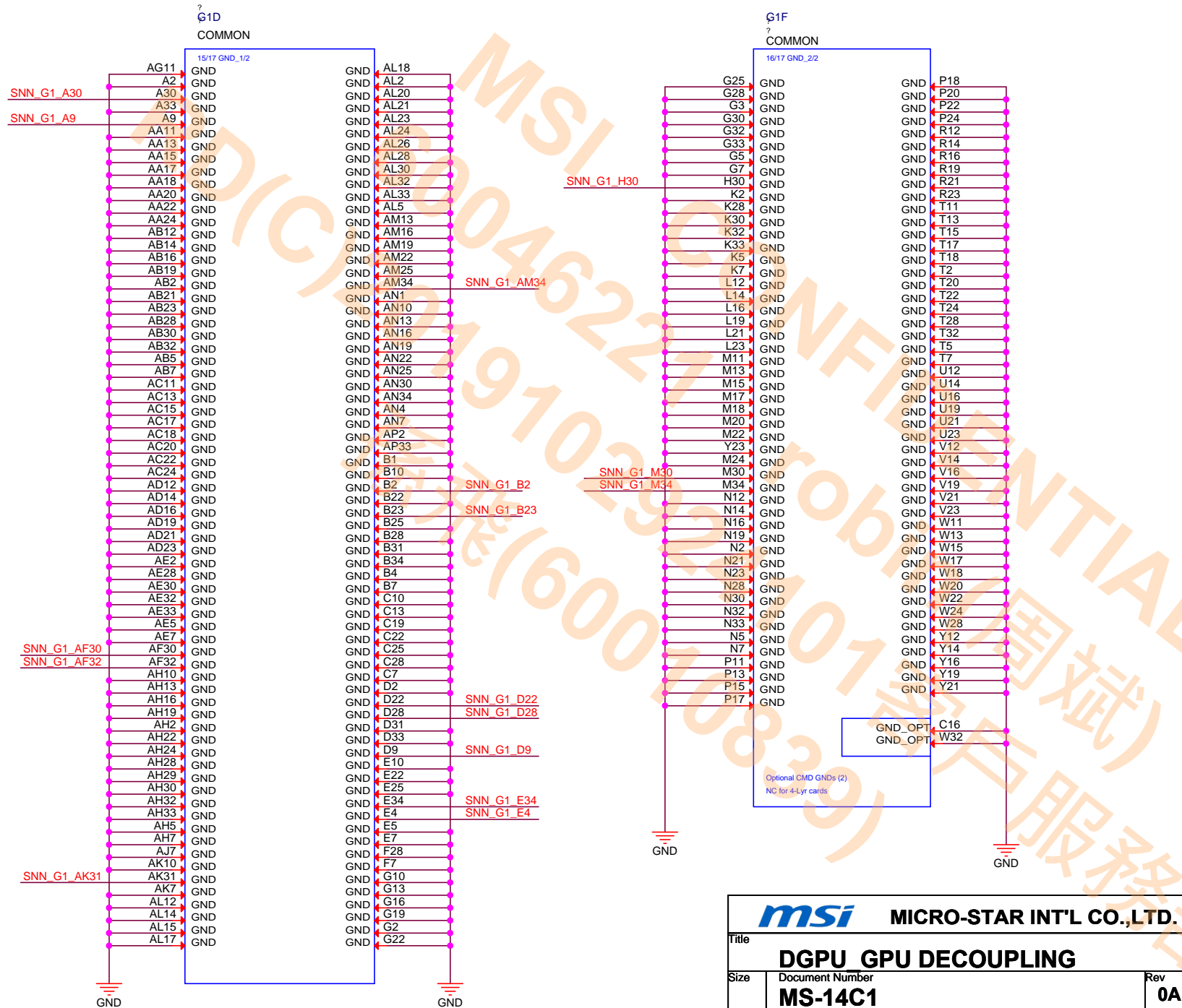
GPU NVVDD, FBVDDQ



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DGPU GND

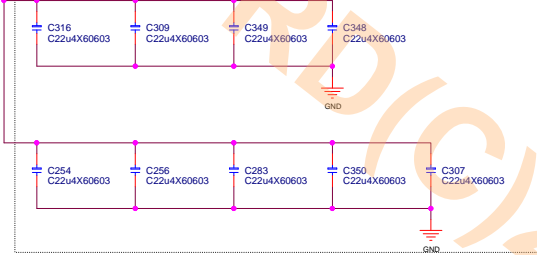


NVVD

N18P
330uF x0
4.7uF x0
22uF x15
10uF x 0+34(Under GPU34,Near GPU0)
0.47uF x26
1uF x0

N17P
330uF x1
4.7uF x2
22uF x10
10uF x 11+21(Under GPU21,Near GPU11)
0.47uF x0
1uF x13

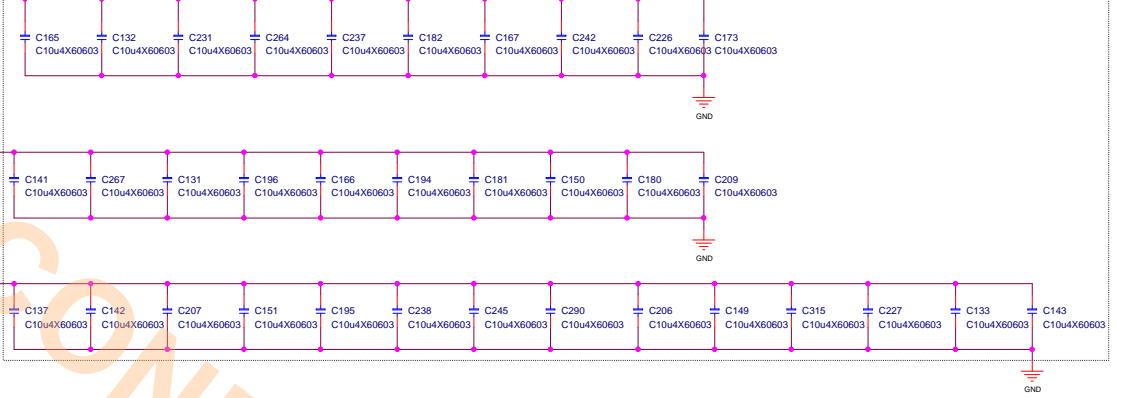
Place Near to GPU 22uF*15pcs



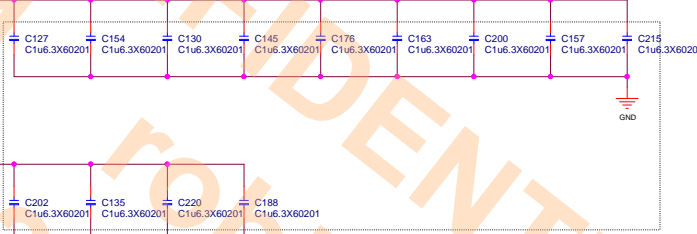
NVVD	1uF X7R	4.7uF X6S	10uF X6S	22uF X6S
N17P	13	2	31	10
N18P	13	0	34	15

GPU DECOUPLING

Place Under to GPU 10uF*34pcs



Place under to GPU 18pcs 1u instead of 0.47u N18 :0.47u*26 change 1u*13

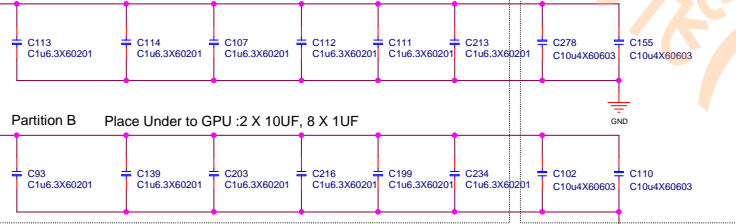


FBVDDQ

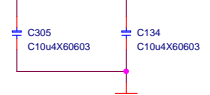
1uF x 16 N18P
10uF x 6
22uF x 5

1uF x 12 N17P
10uF x 6
22uF x 5

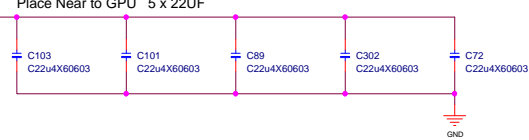
Partition A Place Under to GPU :2 X 10UF, 8 X 1UF N18 :0.47u*24 change 1u*12 Under to GPU :10uF*4



Place Near to GPU 2 x 10UF

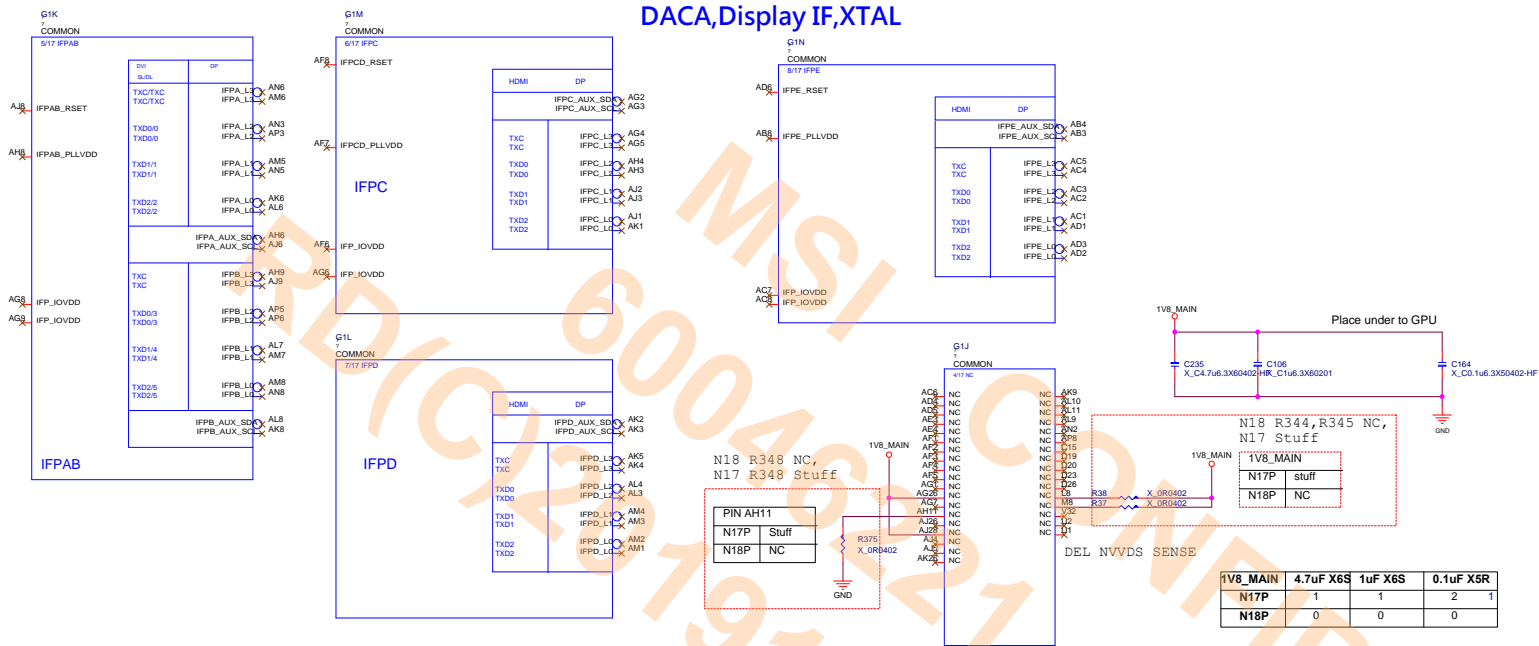
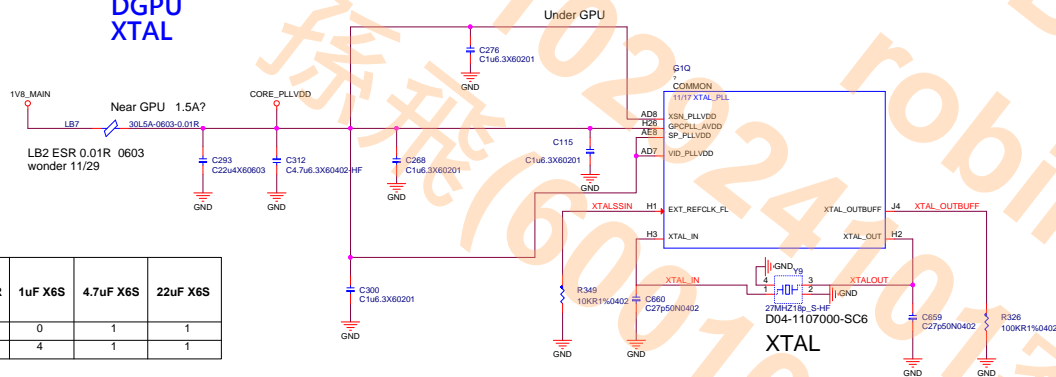


Place Near to GPU 5 x 22UF



FBVDDQ	1uF X7R	10uF X6S	22uF X6S
N17P	12	6	5
N18P	12	6	5

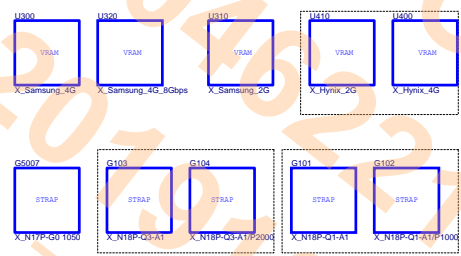
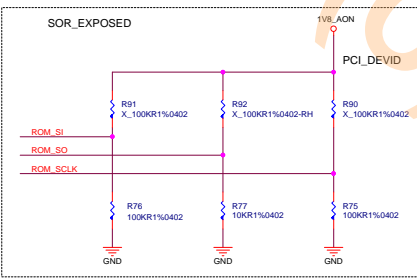
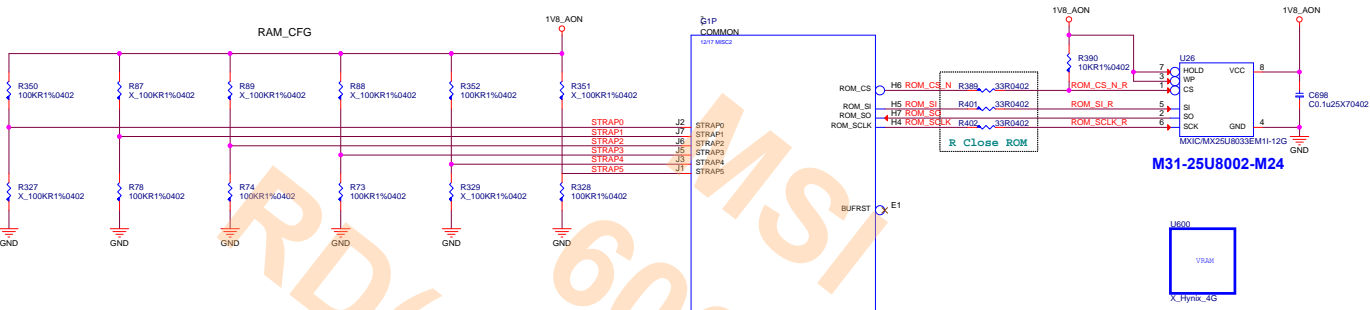
DACA,Display IF,XTAL

DGPU
XTAL

1V8_MAIN	4.7uF X6S	1uF X6S	0.1uF X5F
N17P	1	1	2
N18P	0	0	0

XSN_PLLVDD GPCPLL_AVDD SP_PLLVDD VID_PLLVDD	0.1uF X7R	1uF X6S	4.7uF X6S	22uF X6S
N17P	4	0	1	1
N18P	0	4	1	1

ROM, MULTI-LEVEL STRAPS



GPU	ROM_SO
N17P	100k
N18P	10k

ROM_SO	ROM_SI	ROM_SCLK	SOR_EXPOSED[3:0]	1:ENABLE 0:DISABLE
L	L	L	1111 DEFAULT	SOR0/1/2/3 ENABLE
L	L	L	1110	
L	H	L	1101	
L	H	H	1100	
H	L	L	1011	
H	L	H	1010	
H	H	L	1001	
H	H	H	1000	
L	L	M	0111	
L	M	L	0110	
L	H	M	0101	
L	H	M	0100	
H	L	M	0011	
H	M	L	0010	
H	M	H	0001	
H	H	M	0000	V

ROM_SO	ROM_SI	ROM_SCLK	SOR_EXPOSED[3:0]	1:ENABLE 0:DISABLE
L	L	L	1111 DEFAULT	SOR0/1/2/3 ENABLE
L	L	H	1110	
L	H	L	1101	
L	H	H	1100	
H	L	L	1011	
H	L	H	1010	
H	H	L	1001	
H	H	H	1000	
L	L	M	0111	
L	M	L	0110	
L	H	M	0101	
L	H	M	0100	
H	L	M	0011	
H	M	L	0010	
H	M	H	0001	
H	H	M	0000	V

STRAP2	STRAP1	STRAP0	RAMCFG[4:0]	STRAP Set
L	L	L	0x0 Samsung: M12-8032545-S02 / K4G80325FB-HC28	4GB R116 R120 R388
L	L	H	0x1 Micron: MT51J256M32HF-70-A	R116 R120 R398
L	H	L	0x2 Hynix: M12-5GC8H05-H23 / H5GC8H24MJR-R0C	4GB R116 R127 R388
L	H	H		
H	L	L		
H	L	H		
H	H	L	0x6 Hynix: M12-5GC4HG5-H23 / H5GC4H24AJR-R0C	2GB R129 R127 R388
H	H	H	0x7 Samsung: M12-41325A5-S02/K4G41325FE-HC28	2GB R129 R127 R398
L	L	M	0x8 Micron: EDW032BAG-70-F-A	R116 R120 R398/R388
L	M	L		

STRAP2	STRAP1	STRAP0	RAMCFG[4:0]	STRAP Set
L	L	L	0x0 Samsung: K4G80325FC-HC25 :C	4GB R116 R120 R388
L	L	H	0x1 Micron: MT51J256M32HF-80:B	4GB R116 R120 R398
L	H	L	0x2 Hynix: H5GC8H24AJR-R2C :A	4GB R116 R127 R388

1:SMB_ALT_ADDR ENABLE
0:SMB_ALT_ADDR DISABLE

1:DEVID_SEL REBRAND
0:DEVID_SEL ORIGINAL

1:PCIE_CFG LOW POWER
0:PCIE_CFG HIGH POWER

1:VGA_DEVICE ENABLE
0:VGA_DEVICE DISABLE

H=High :Tied to 1.8V
M=Middle:Tied to 0.9V
L=Low :Tied to 0V

STRAP5	STRAP4	STRAP3	SMB_ALT_ADDR	DEVID_SEL	PCIE_CFG	VGA_DEVICE
L	L	L	0	0	0	0
L	L	L	0	0	0	0
M	H	H	1	1	1	1
M	H	L	1	1	1	0
M	L	H	1	1	0	1
M	L	L	1	1	0	0
L	H	M	1	0	1	1
L	M	H	1	0	1	0
L	M	L	1	0	0	1
L	L	M	1	0	0	0
H	H	H	0	1	1	1
H	H	L	0	1	1	0
H	L	H	0	1	0	1
H	L	L	0	1	0	0
L	H	H	0	0	1	1
L	H	L	0	0	1	0
L	L	H	0	0	0	1 DEFAULT
L	L	L	0	0	0	0 V

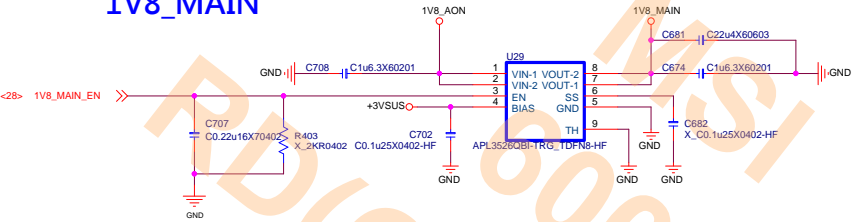
[illegible]

NVIDIA Power Sequence Control

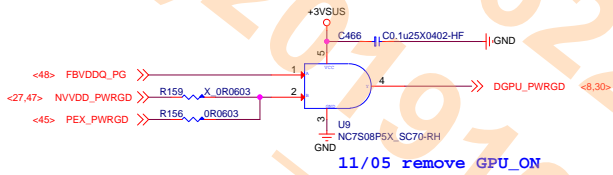
Power on = 1V8_AON -> 1V8_MAIN -> 3V3_NV/NVDD -> NVDDS/PEX_VDD -> FBVDDQ -> DGPUPWRGD

Power down = NVDDS -> PEX_VDD -> NVVDD/FBVDDQ -> 3V3_NV -> 1V8_MAIN -> 1V8_AON

1V8_MAIN

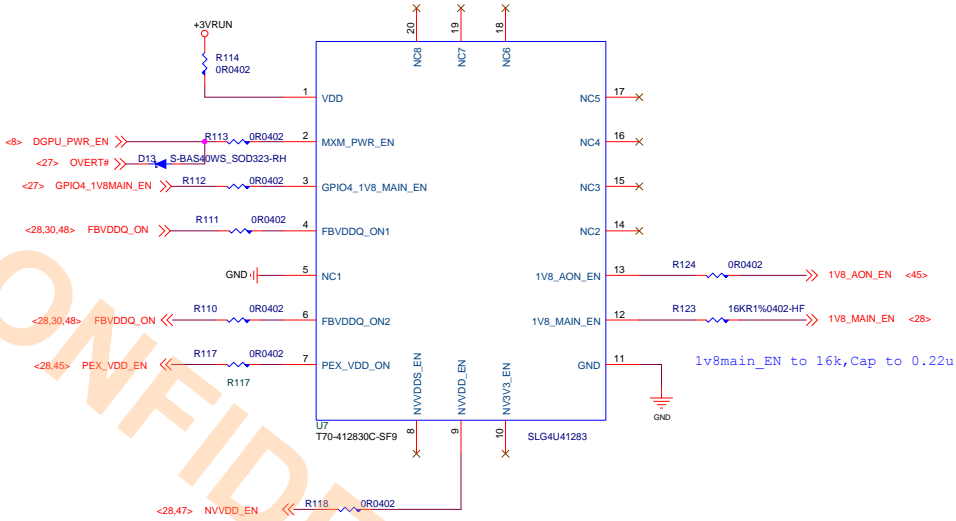


DGPU POWER GOOD

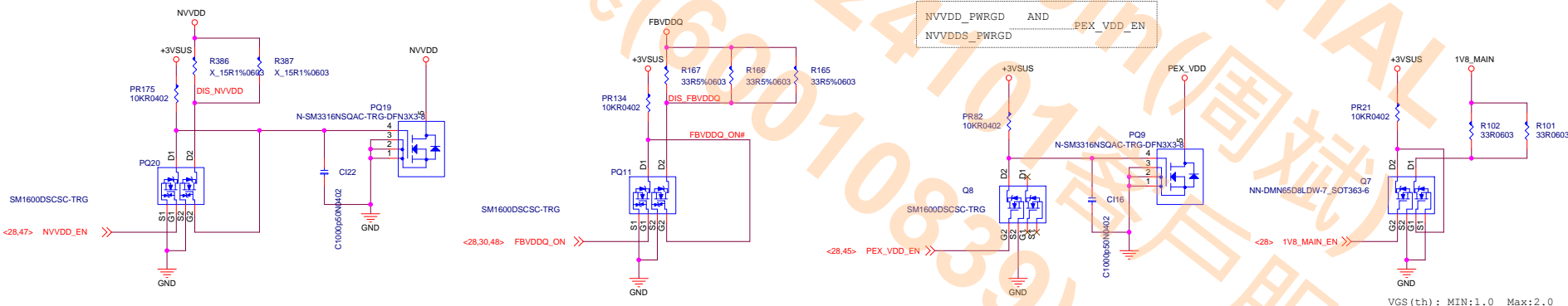


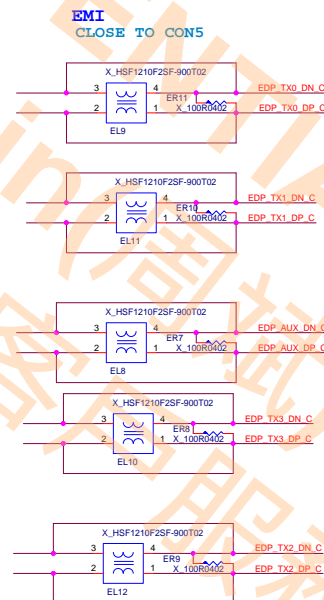
11/05 remove GPU_ON

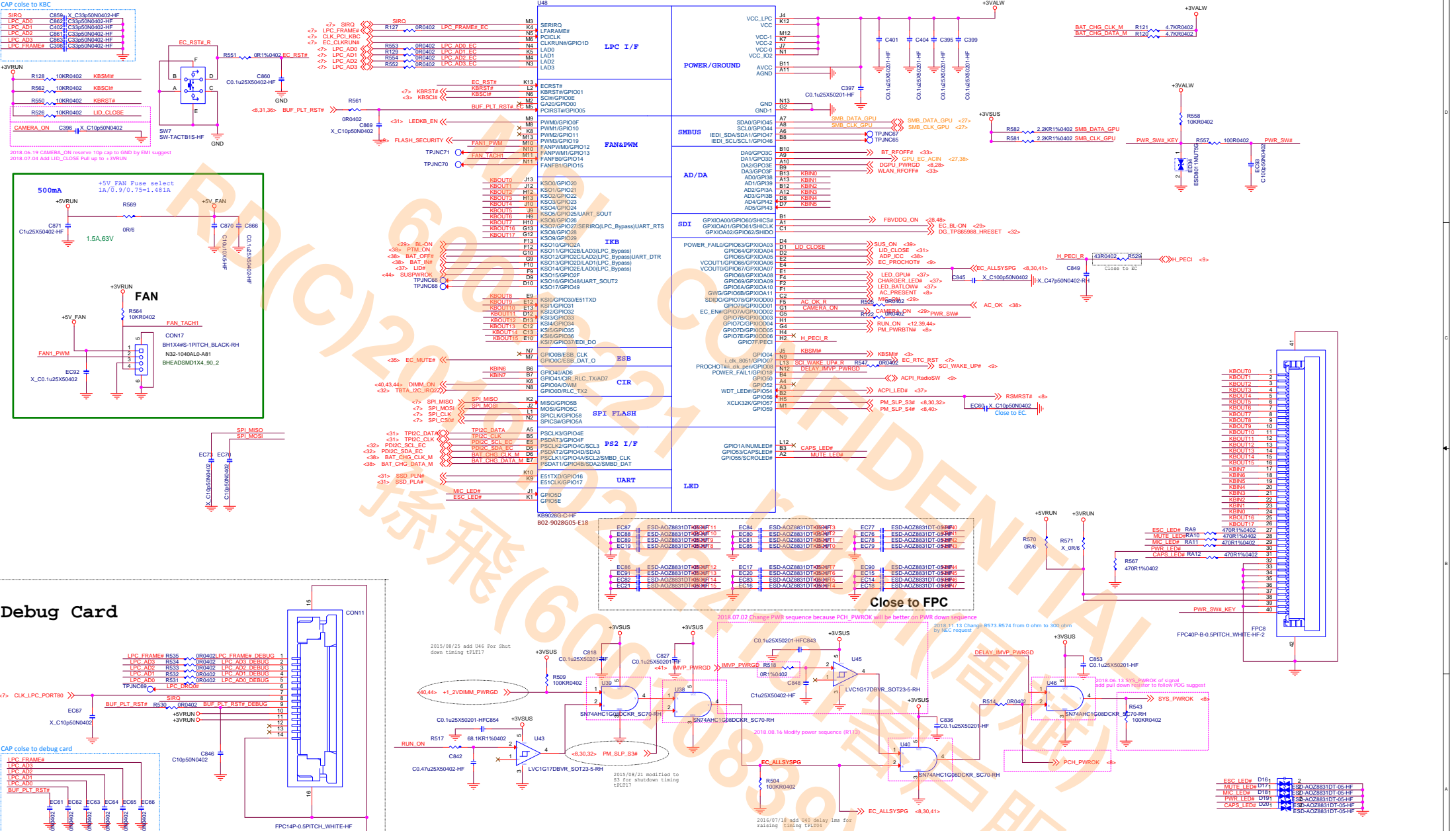
SLG4U41283 power sequence control IC



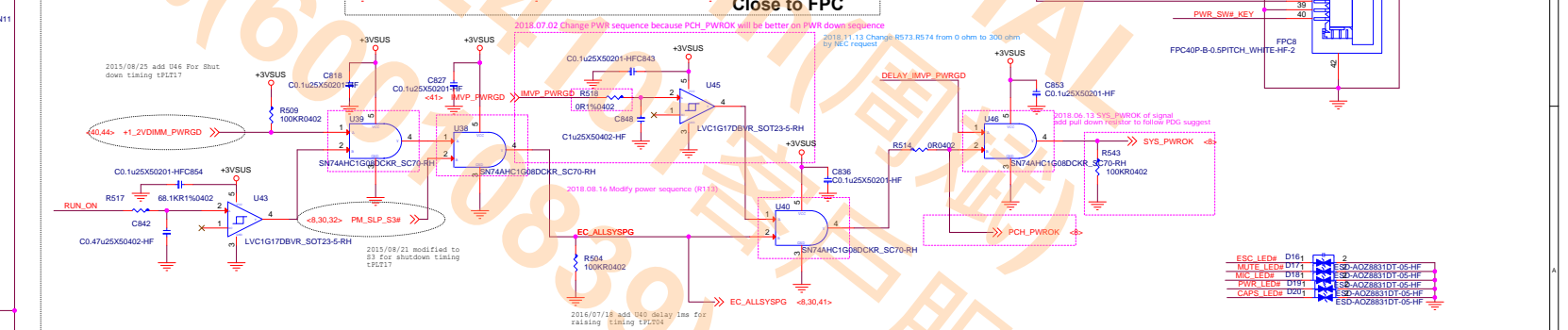
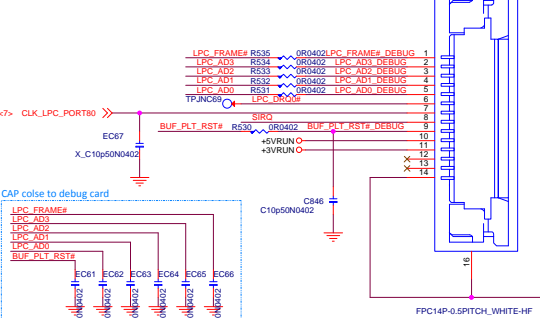
Discharge



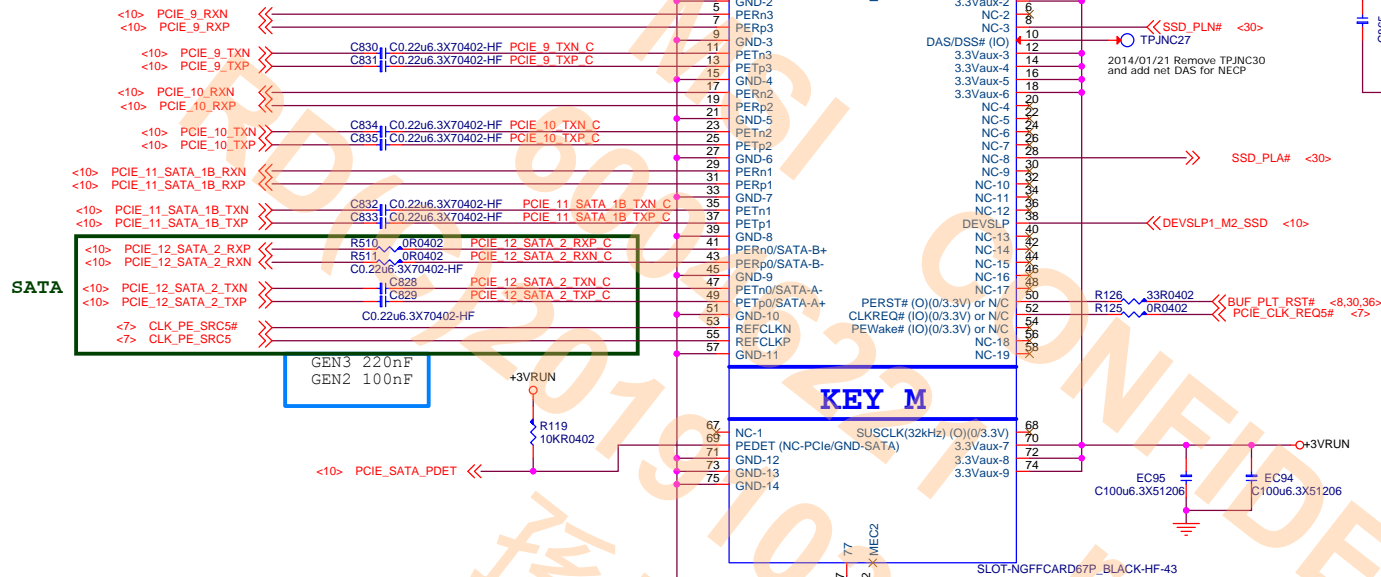




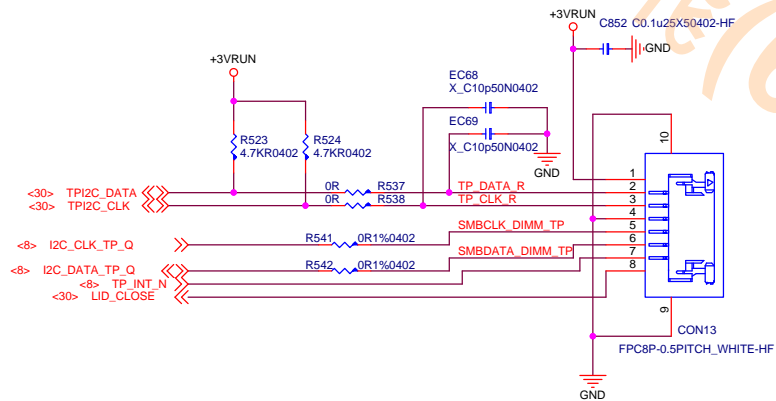
Debug Card



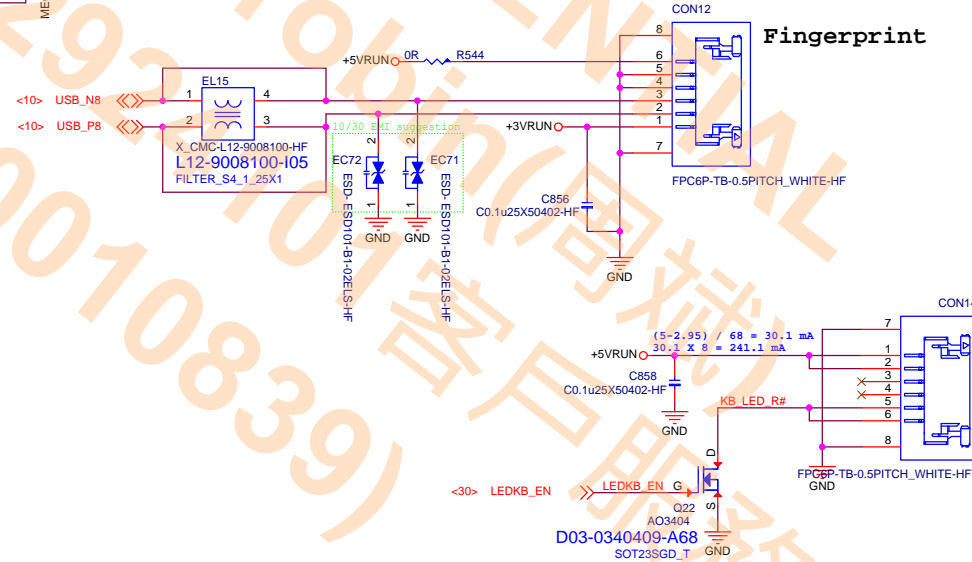
PCIEx4 /SATA Reversal SSD

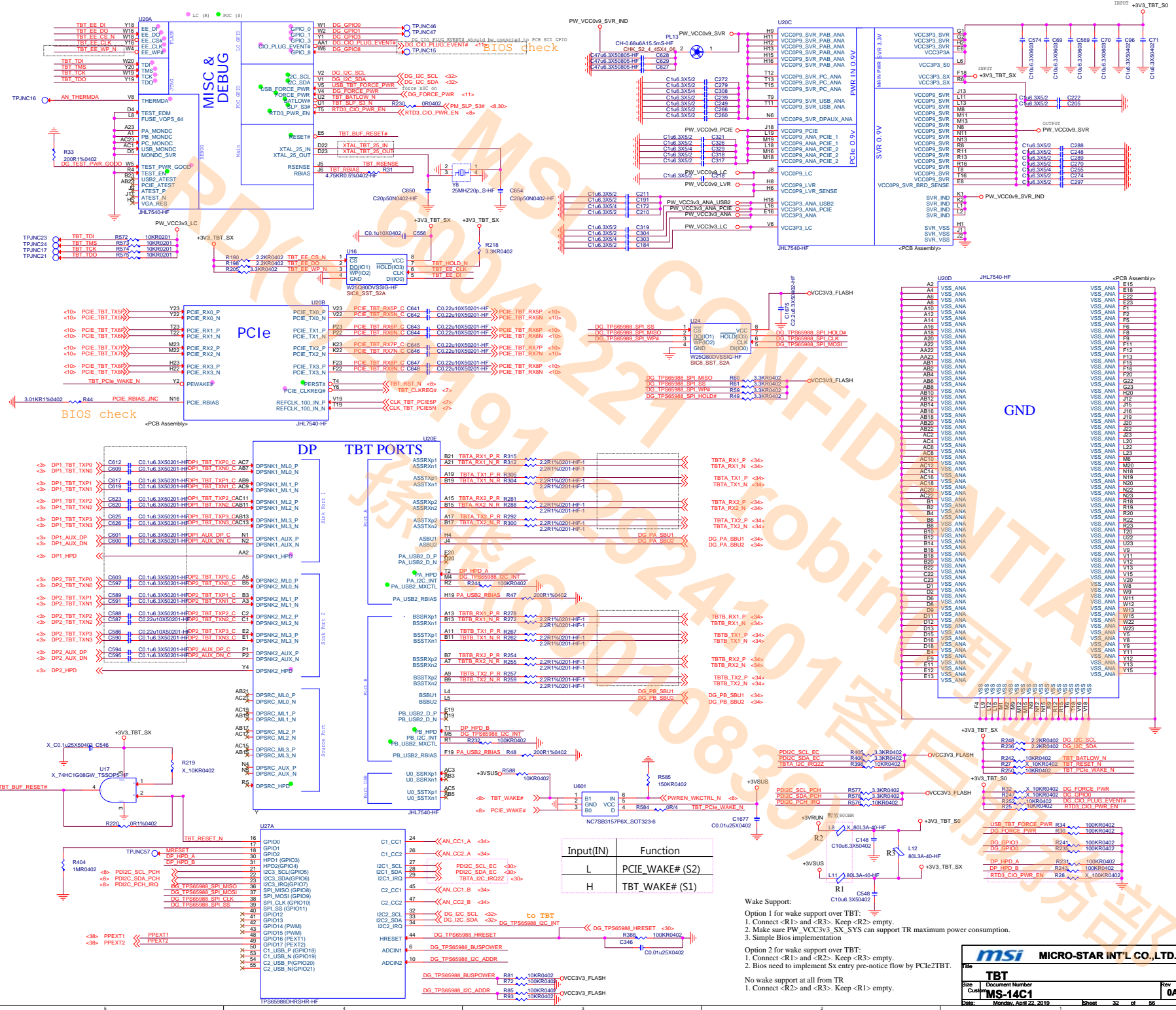


Click Pad



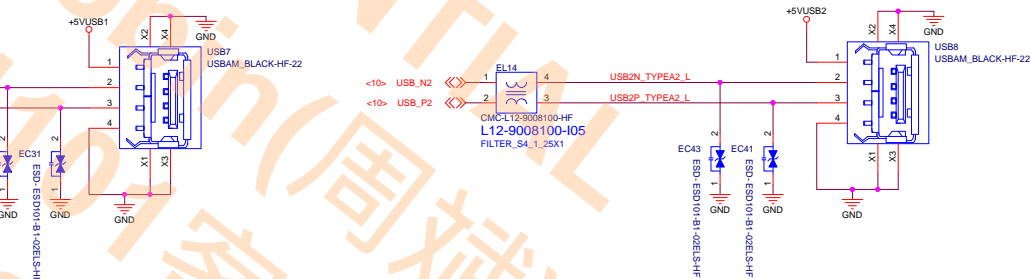
Fingerprint





Input(IN)	Function
L	PCIE_WAKE# (S2)
H	TBT_WAKE# (S1)

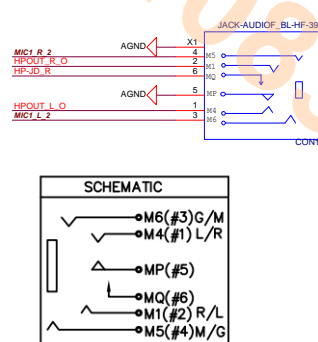
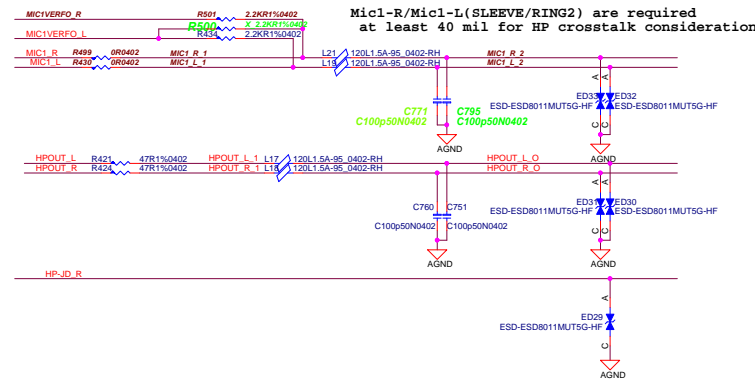
- Wake Support:
- Option 1 for wake support over TBT:
1. Connect <R1> and <R3>. Keep <R2> empty.
 2. Make sure PW_VCC3V3_SX SYS can support TR maximum power consumption.
 3. Simple BIOS implementation
- Option 2 for wake support over TBT:
1. Connect <R1> and <R2>. Keep <R3> empty.
 2. Bios need to implement Sx entry pre-notice flow by PCIeT2BT.
- No wake support at all from TR
1. Connect <R2> and <R3>. Keep <R1> empty.



Type C USB3.1

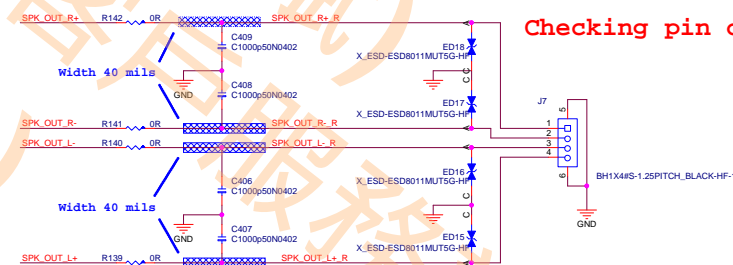


Universal Jack

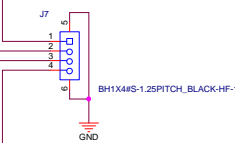


SPEAKER

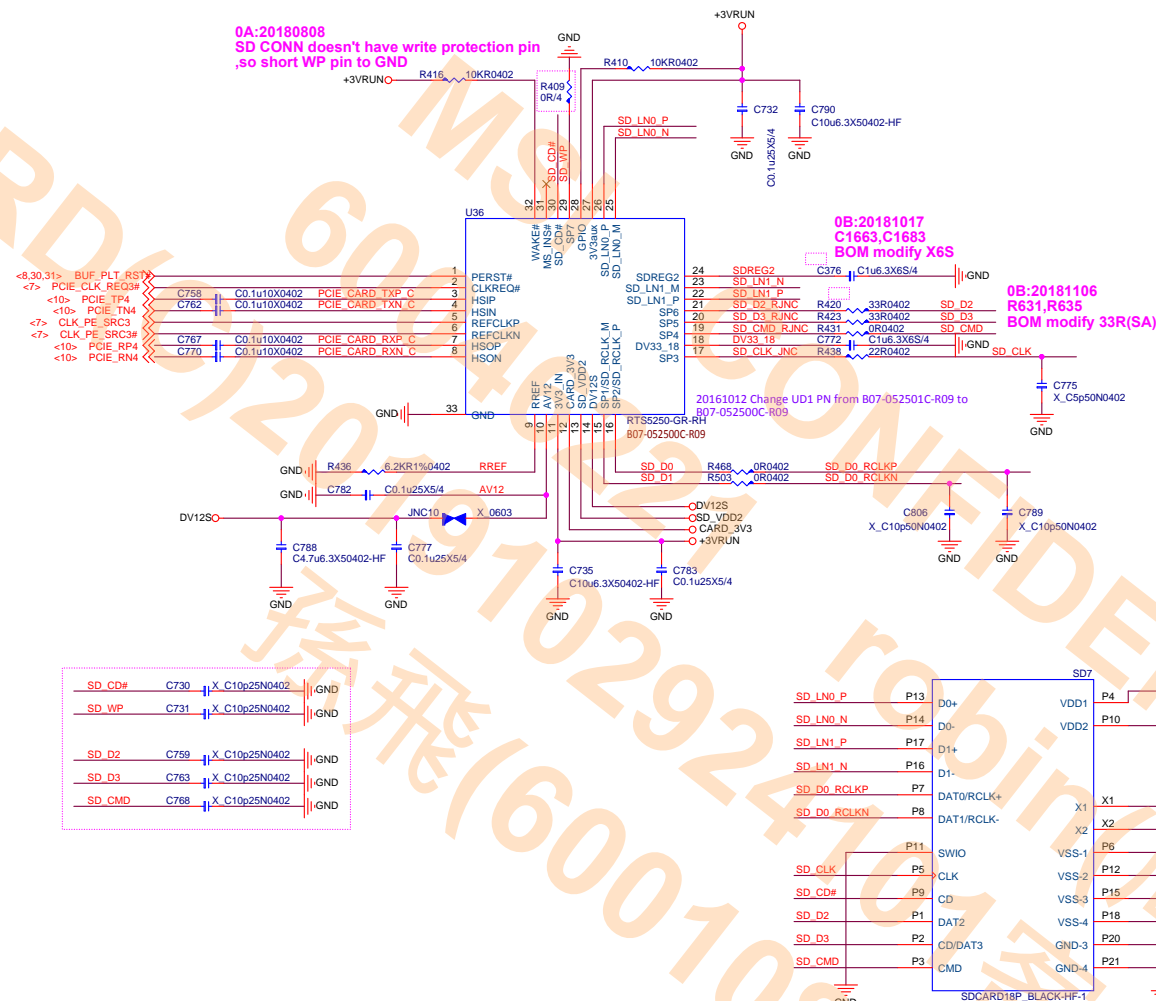
- 1.SPK L+ L- R+ R- trace width: Speaker 4 ohm ==> 40 mils
Speaker 8 ohm ==> 20 mils
- 2.If you mount the LC filter (L1+L4;C4/C11;C2/C7/C10/C13).Please let them together and close to codec.
- 3.Please make the trace length/ Speaker wire length of SPKL+/L-/R+/R- be the same as possible as you can.
- 4.If L1,L2,L3,L4 are replaced by 0 ohm/1.6A resistor(please don't use general bead, because it may influence the THD+N quality), and C4,C11 should be NC




Checking pin define

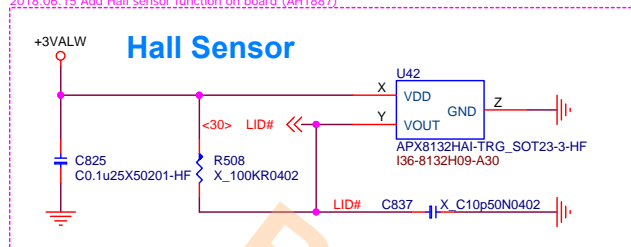


CardReader (RTS5250)



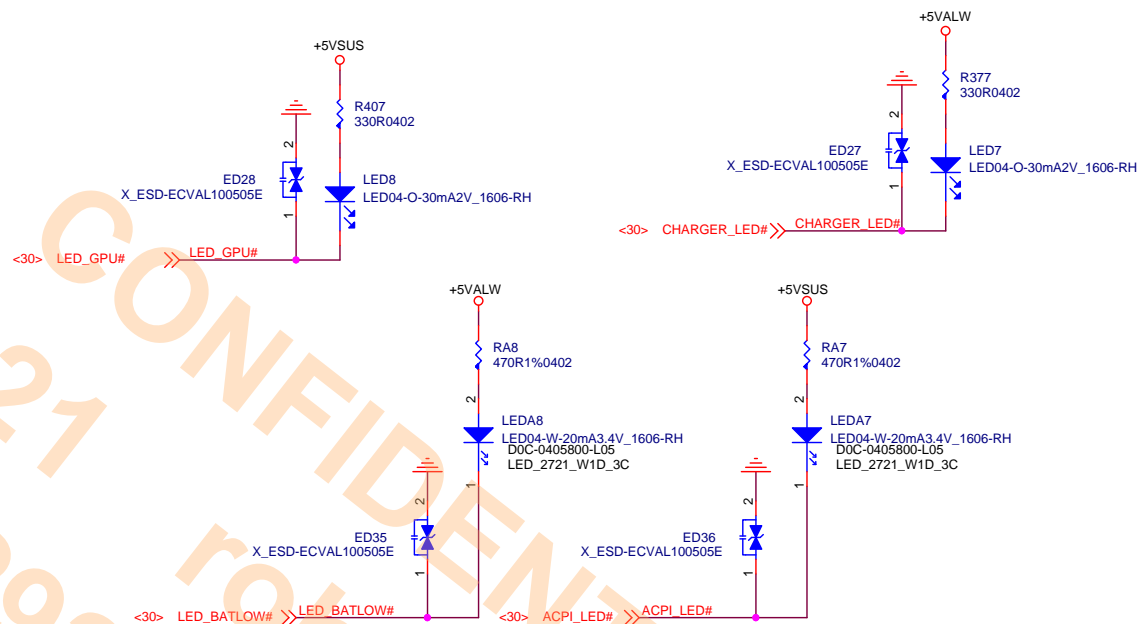
 MICRO-STAR INT'L CO.,LTD.	
Title Card Reader(RTS5250)	
Size Customer	Document Number MS-14C1
Date: Monday, April 22, 2019	Sheet 36 of 56

2018.06.20 Change hall sensor IC from AH1887 (2 output) to AH1810 (1 output)
2018.06.15 Add Hall sensor function on board (AH1887)



2018.06.26 Change hall sensor IC from AH1810 to APX8132 by ME suggest

LED



MICRO-STAR INT'L CO.,LTD.

Title

PWR SW/FP/LED/LID

Size
Custom

Document Number
MS-14C1

Rev
0A

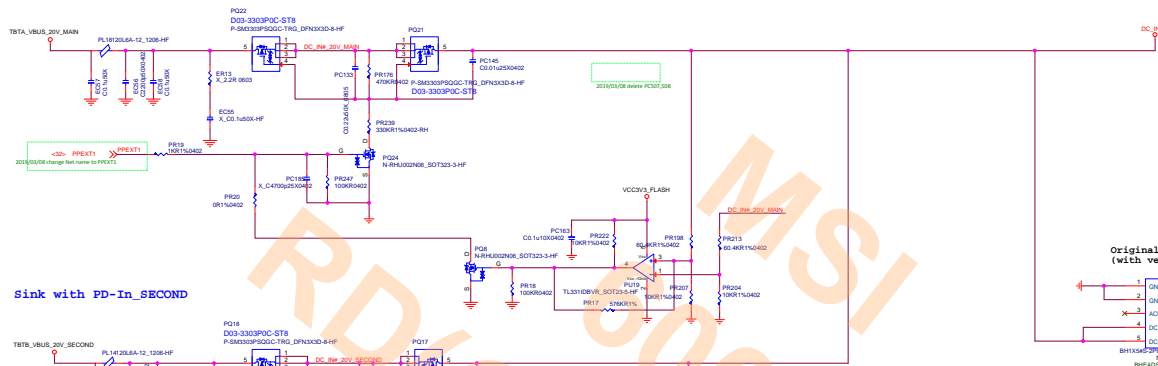
Date:

Monday, April 22, 2019

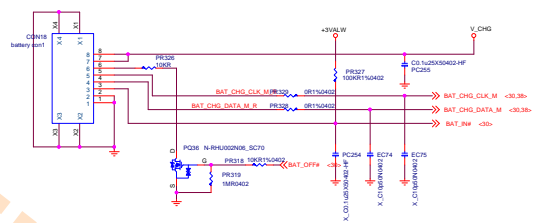
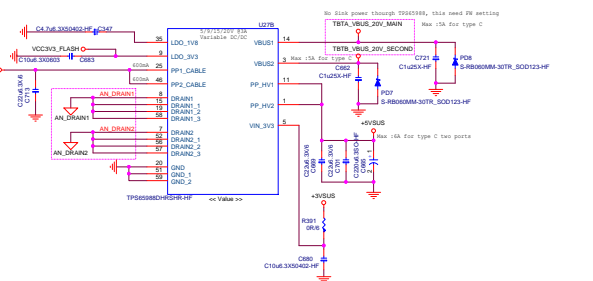
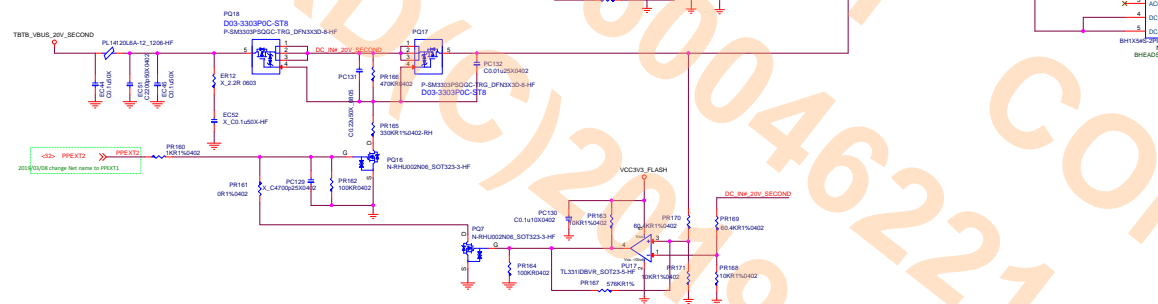
Sheet

37 of 56

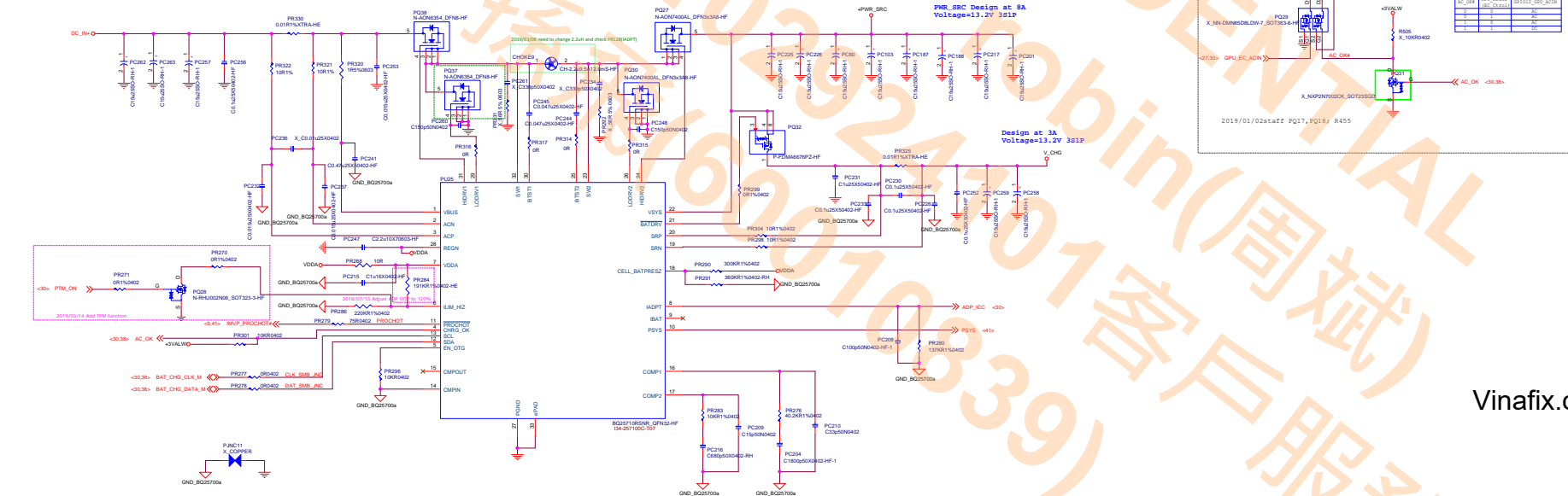
Sink with PD-In_MAIN



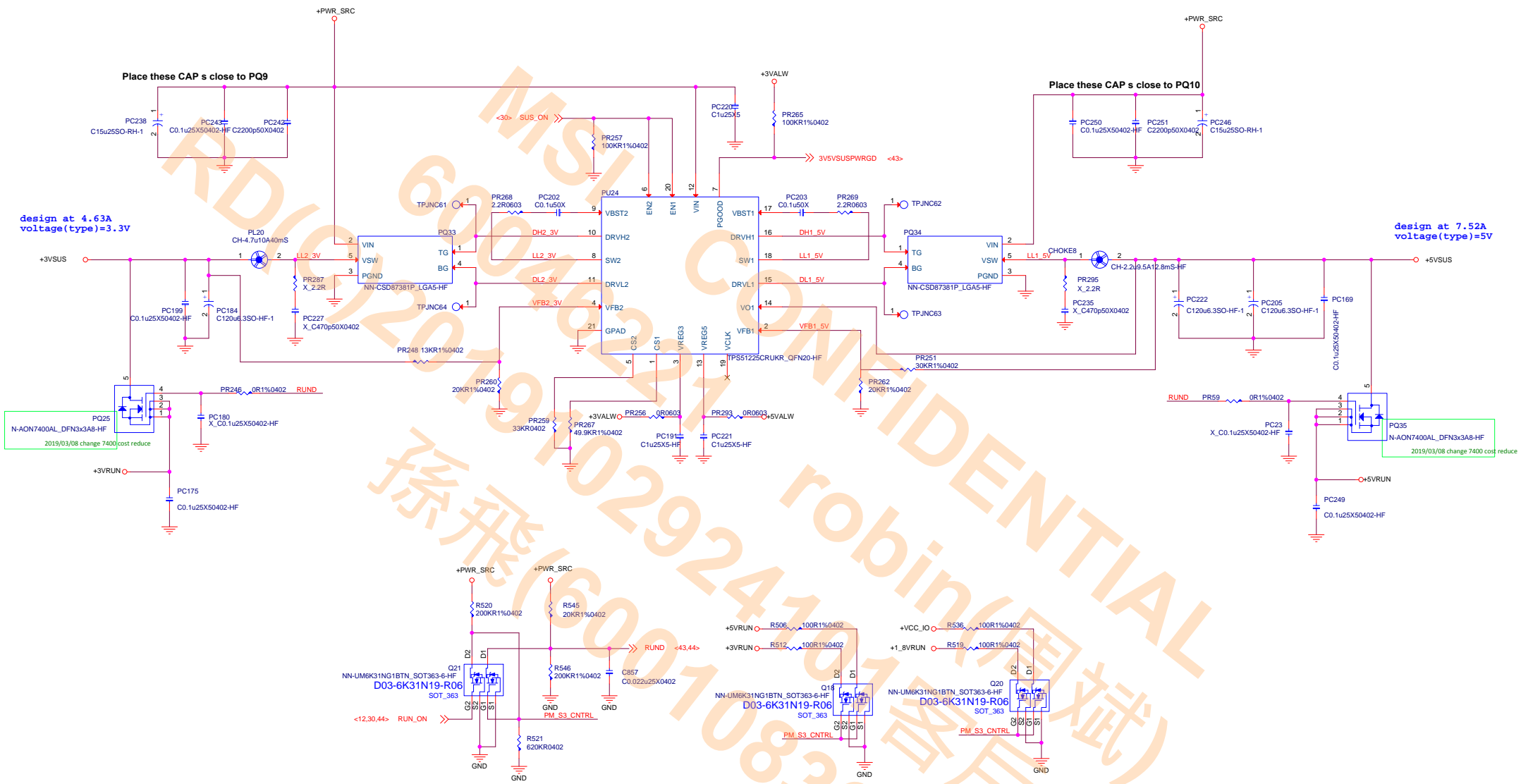
Sink with PD-In SECOND

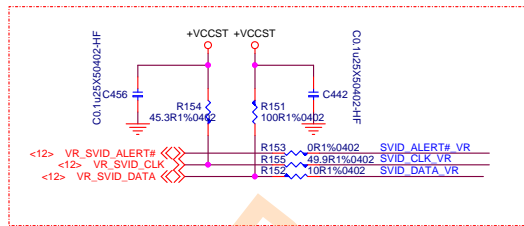


Battery Charger



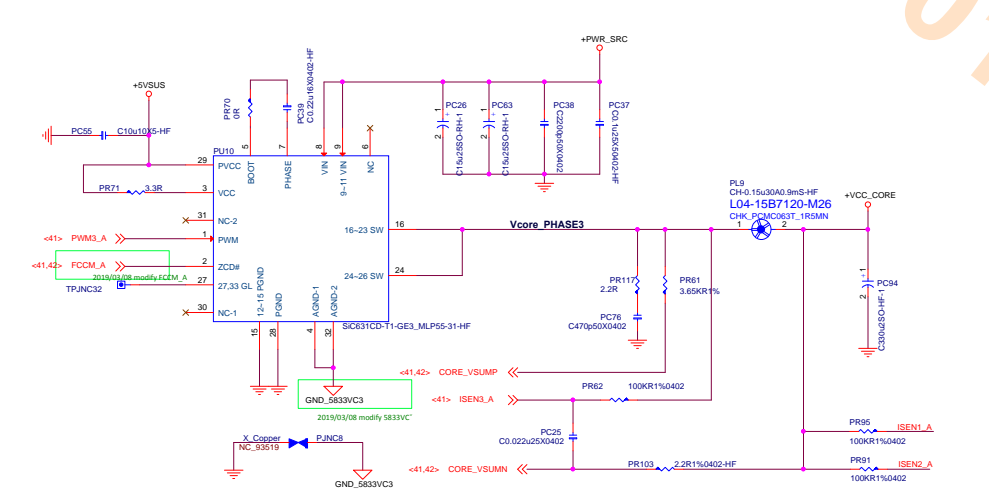
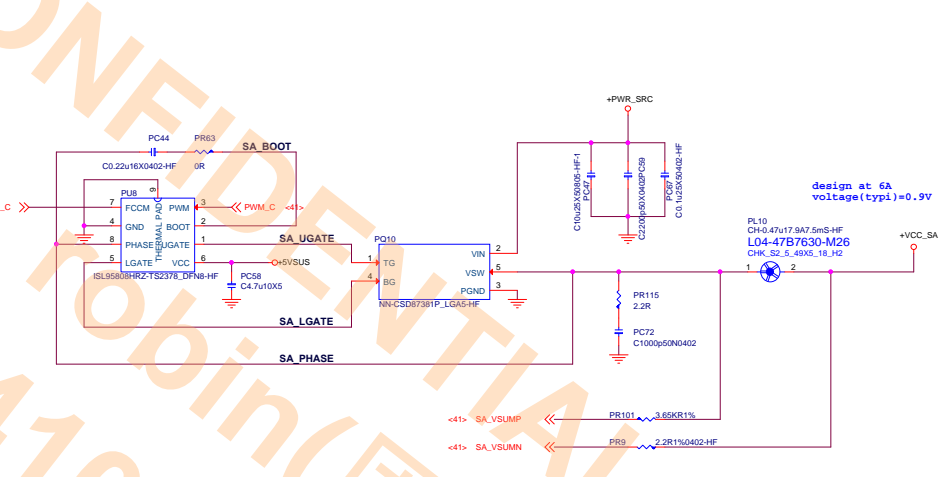
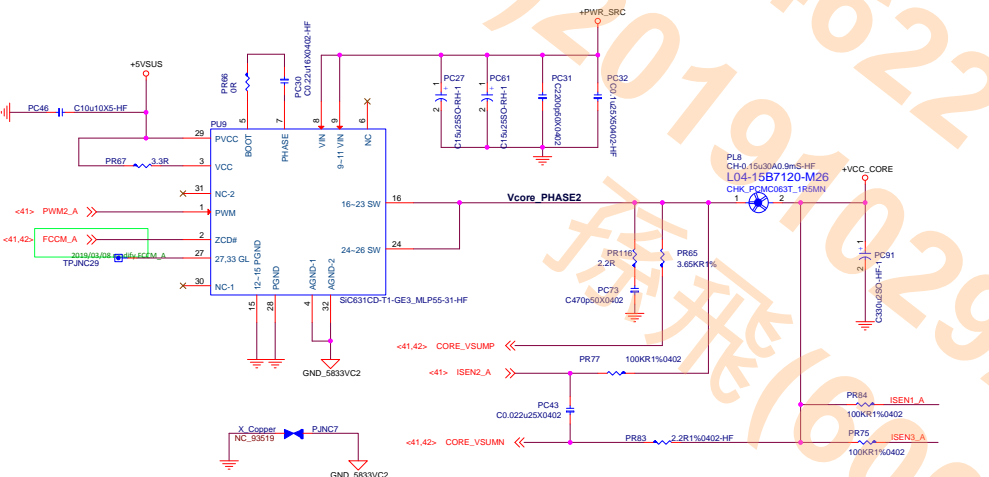
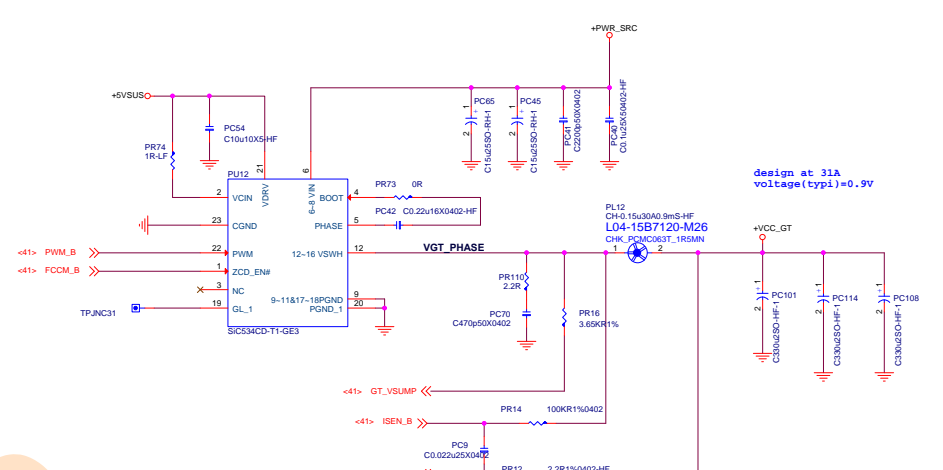
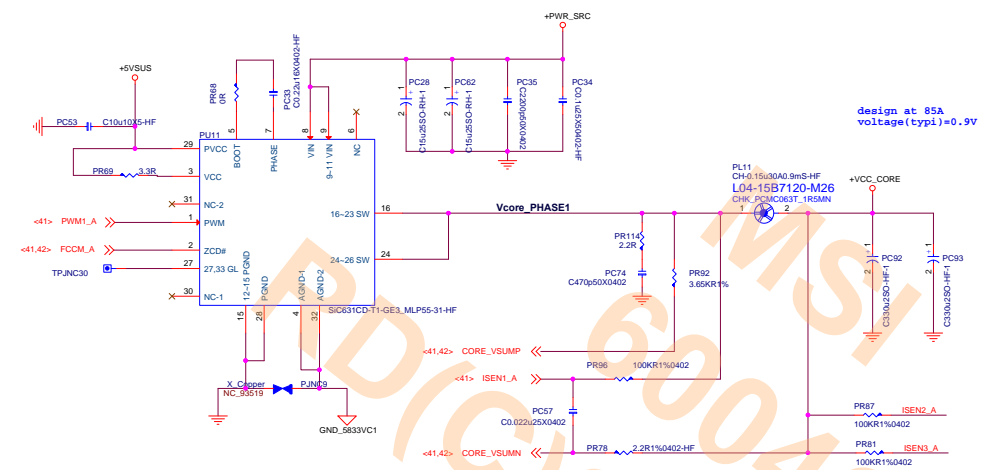
Vinafix.com

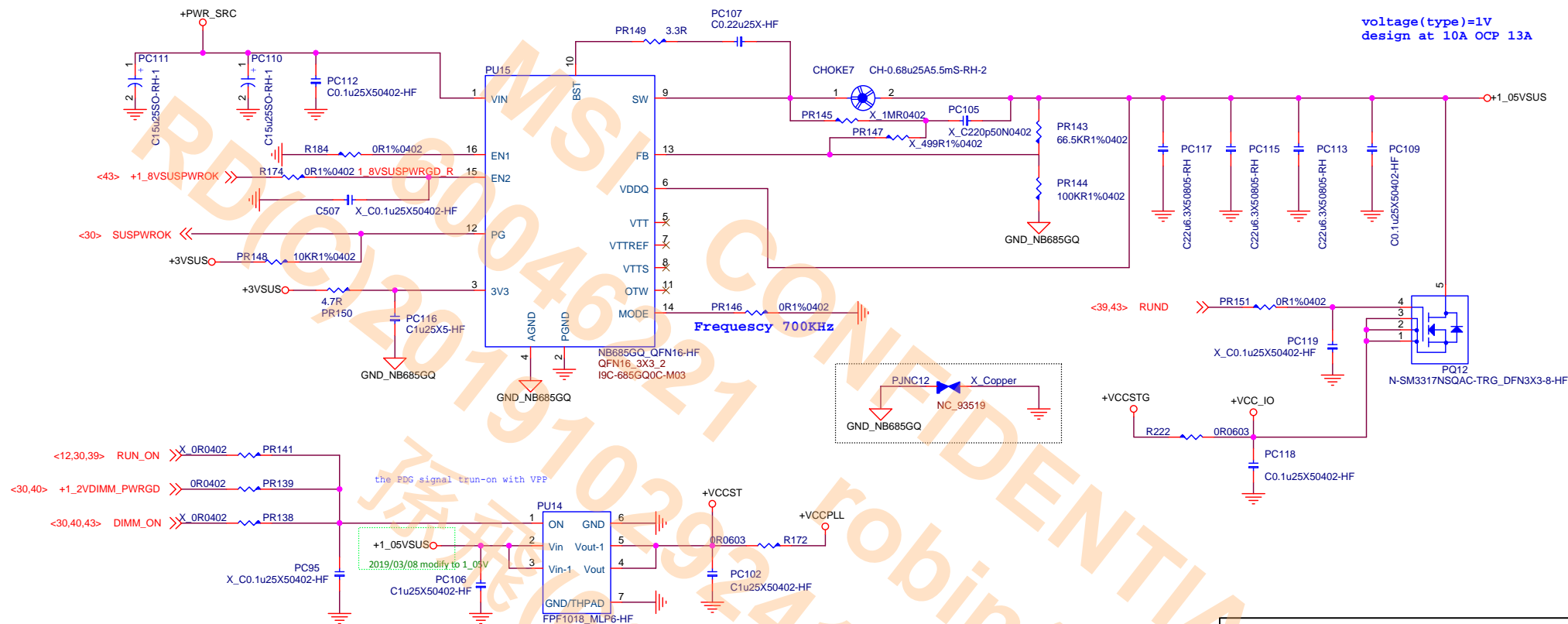





2019/03/08
Vpsys= 1.2V, Rpsys=133W
(Rpsys=Vpsys/Rpsys/Kpsys)
(Kpsys is 1uA/W, Rpsys is 9.09Kohm)

teknisi indonesia



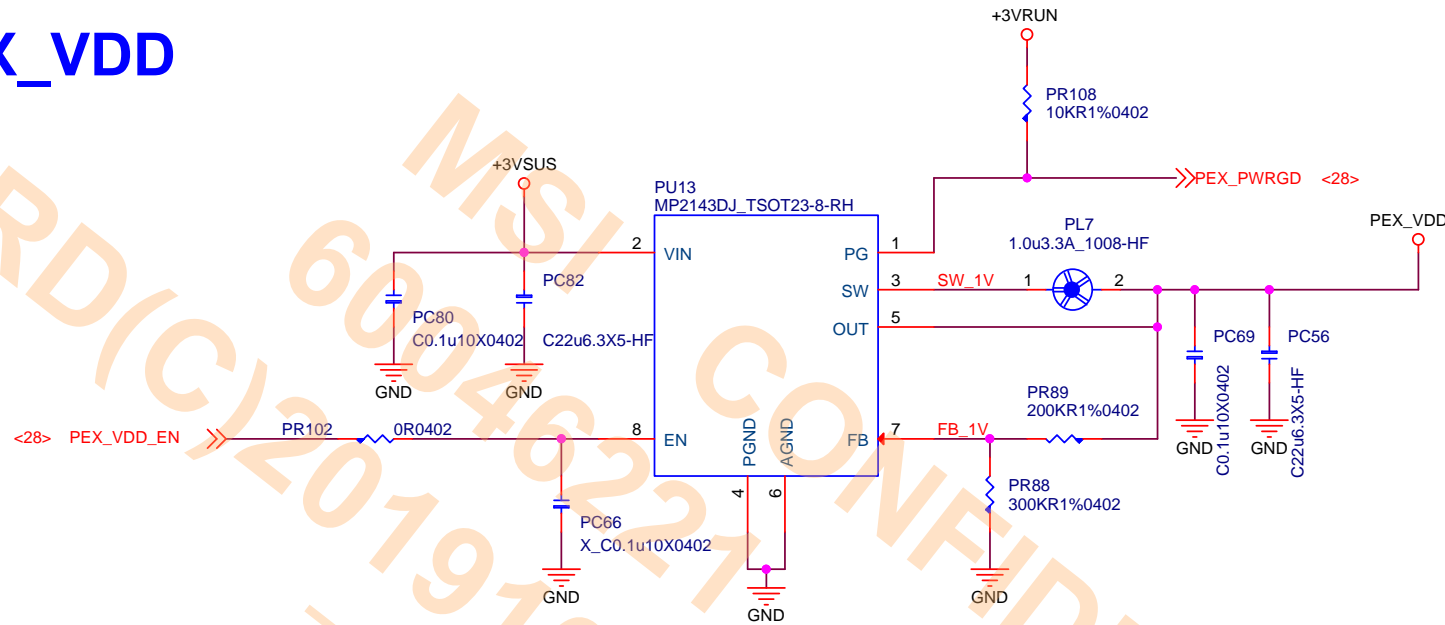


		MICRO-STAR INT'L CO.,LTD.	
Title			
+1 05VSUS;+VCCST;+VCCIO			
Size	Document Number		Rev
Custom	MS-14C1		0A
Date:	Monday, April 22, 2019	Sheet	44 of 56

PEX_VDD

PEX_VDD

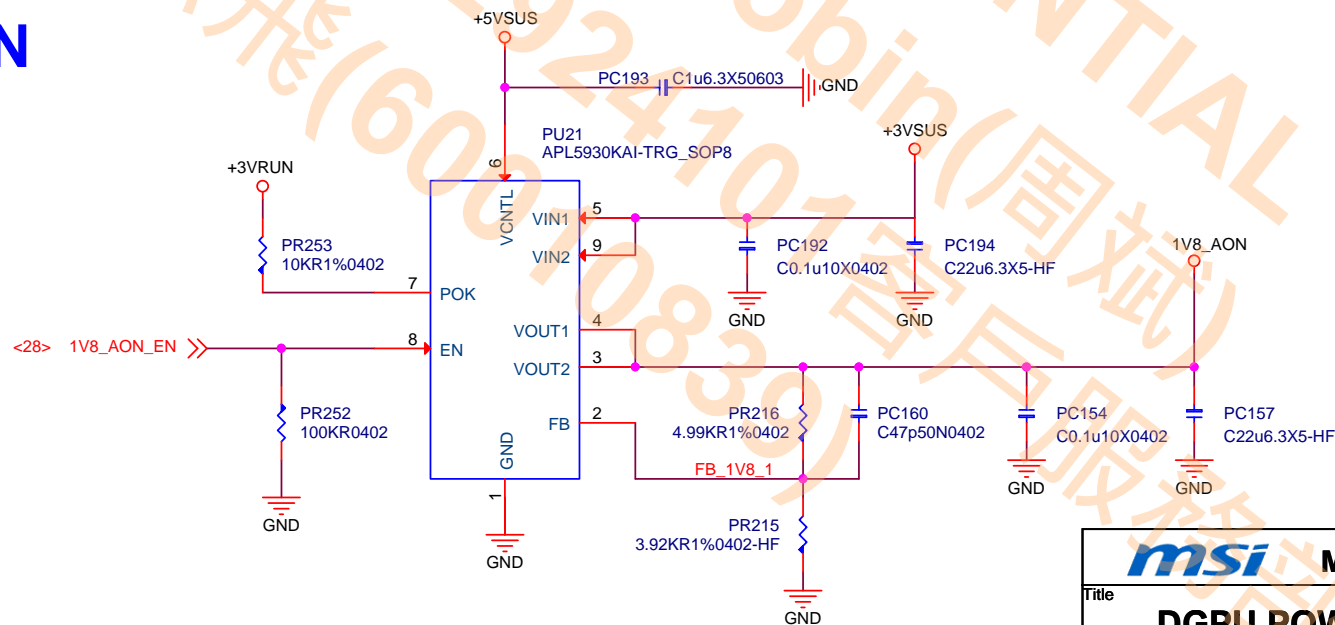
Voltage = 1.0V
Current = 1.6A
OCP(typi) = 4.8A



1V8_AON

1V8_AON

Voltage = 1.8V
Current = 2.3A



msi

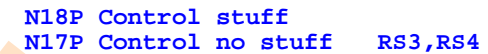
MICRO-STAR INT'L CO.,LTD.

Title **DGPU POWER PEX_VDD/1V8_AON**

Size Custom Document Number **MS-14C1** Rev **0A**

Date: Monday, April 22, 2019 Sheet 45 of 56

<27> GPIO22_OC_WARN >>

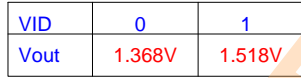


OnSemi	PR54, PR55	PR41, PR61	PR43	PR45, PR51	PC21, PC26
CONFIG	R954, R924	R977, R923	R950	R953, R952	C841, C836
N18P-G0	649R	475R	243K	75K	1.0nF

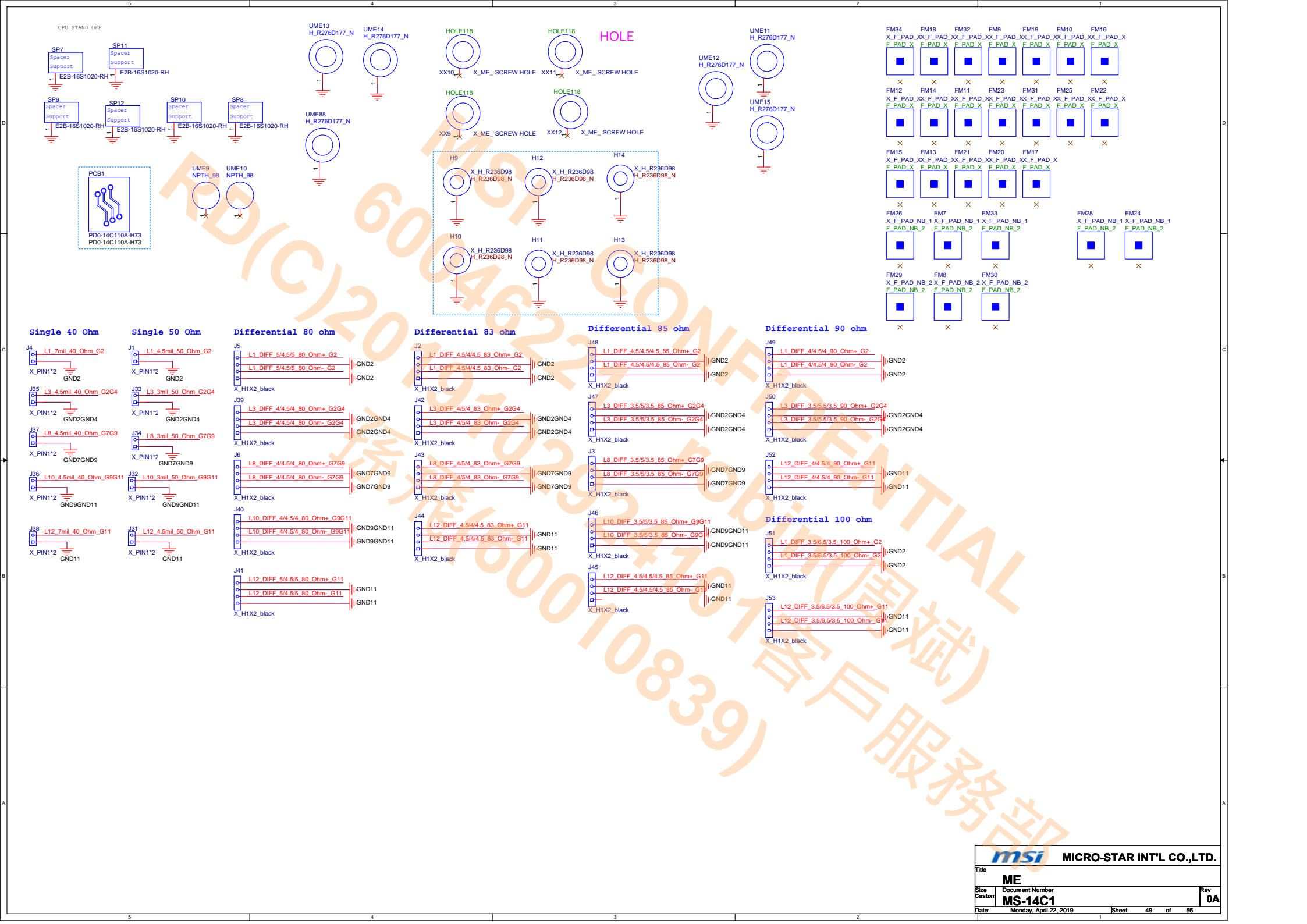
EDP-Peak 150A
EDP-Con 35A for N18P-G0 MAX-Q

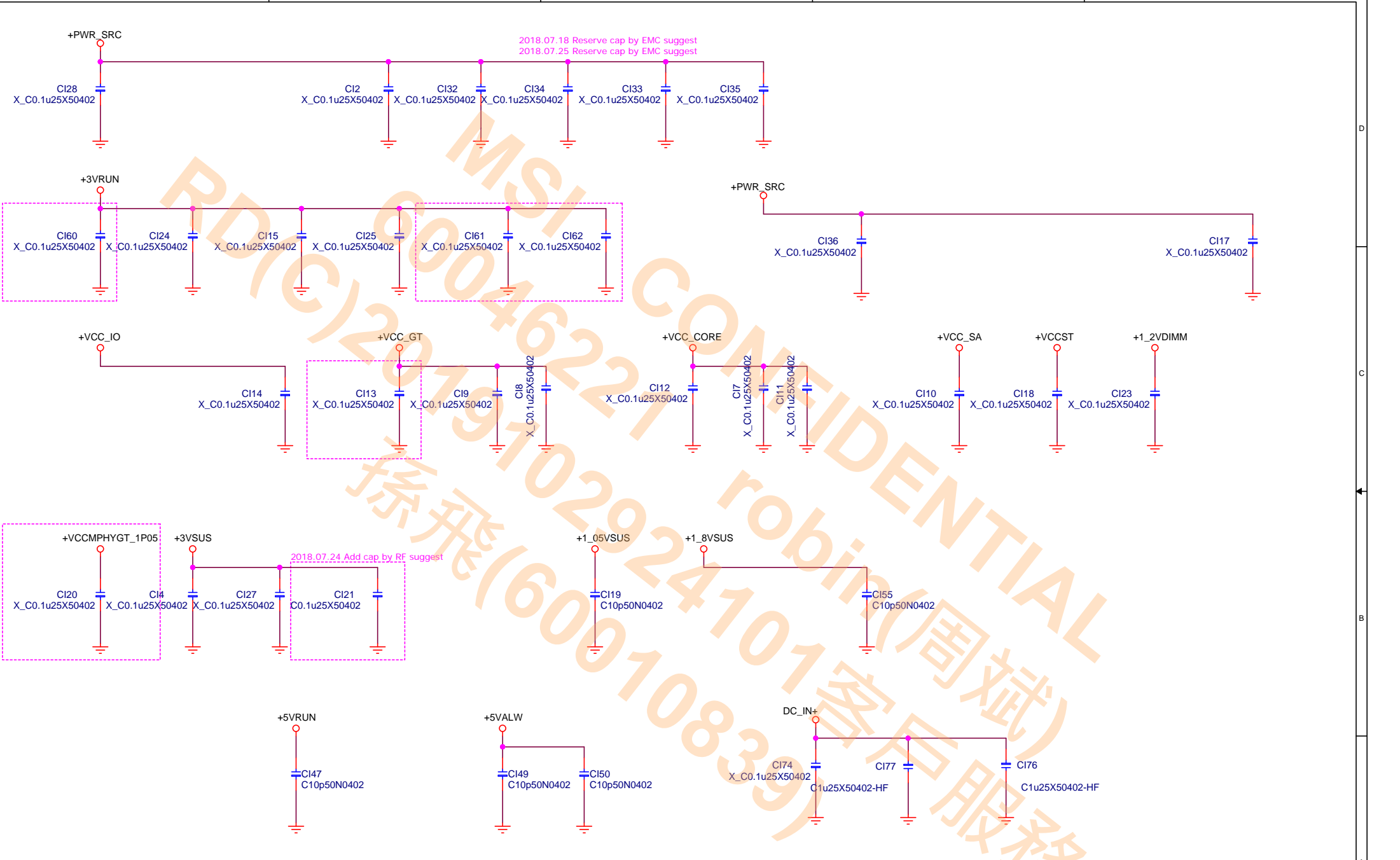


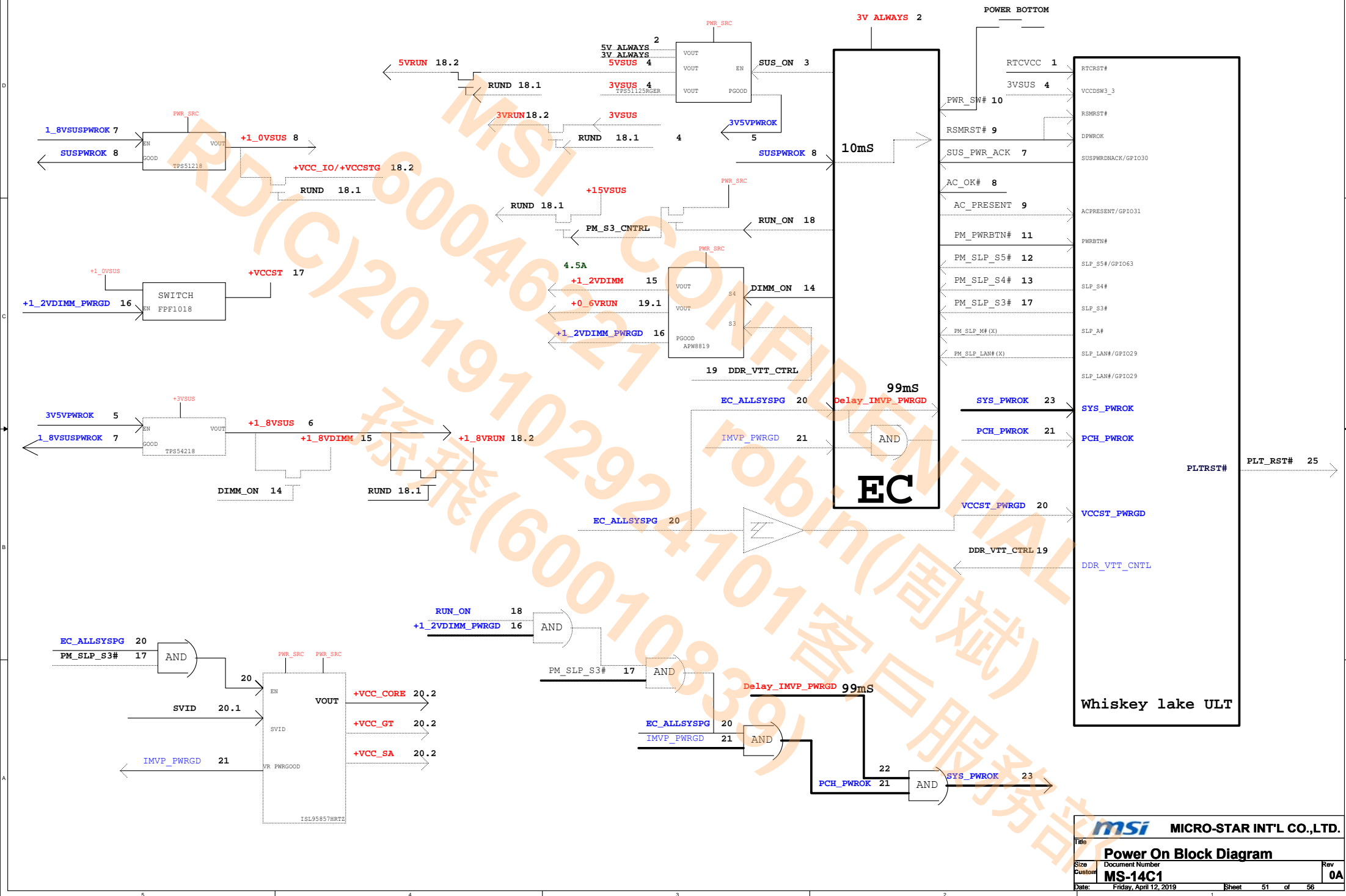
Vboot=1.498V



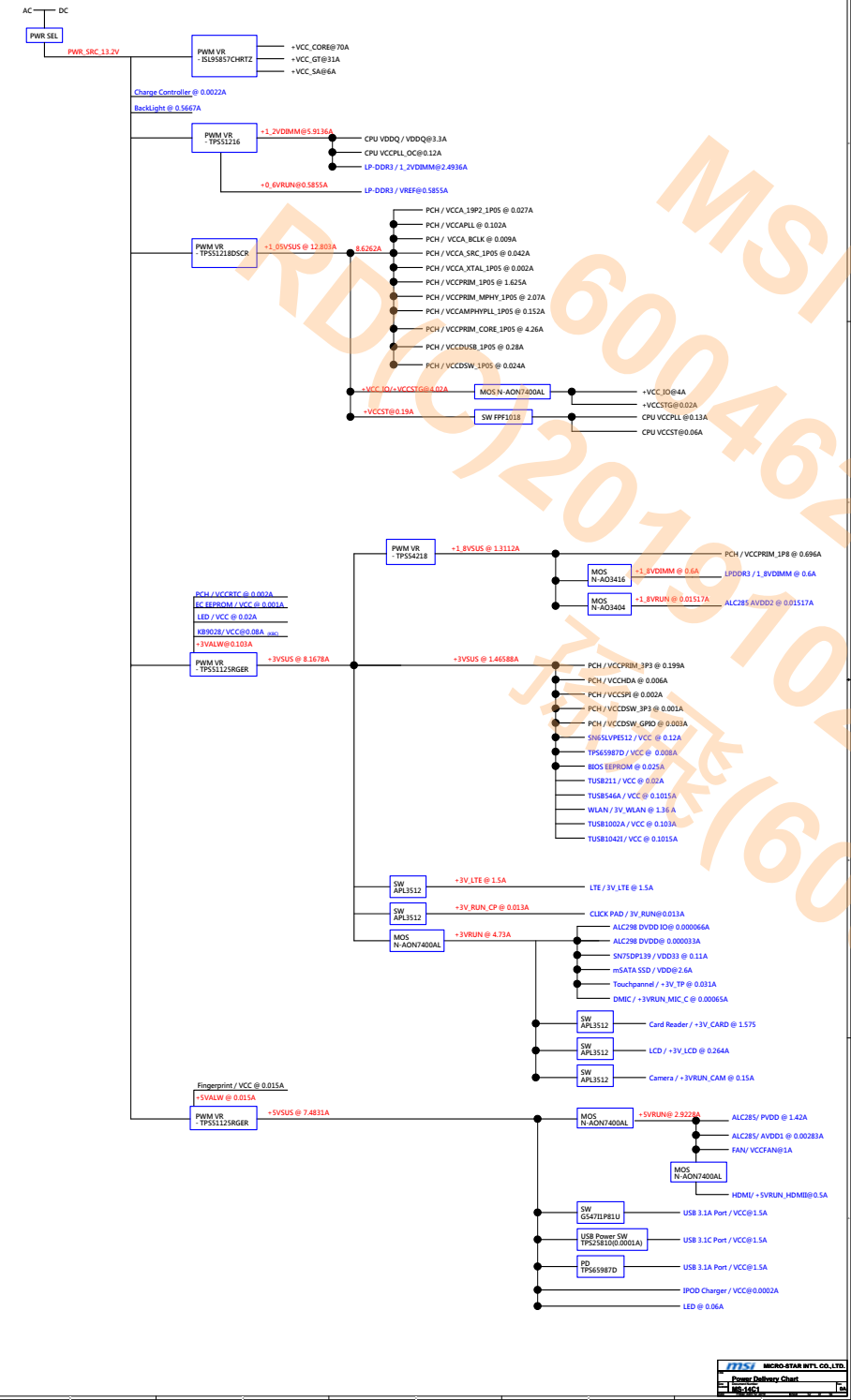
FBVDDQ
EDP-Con 14A
EDP-Peak 20A



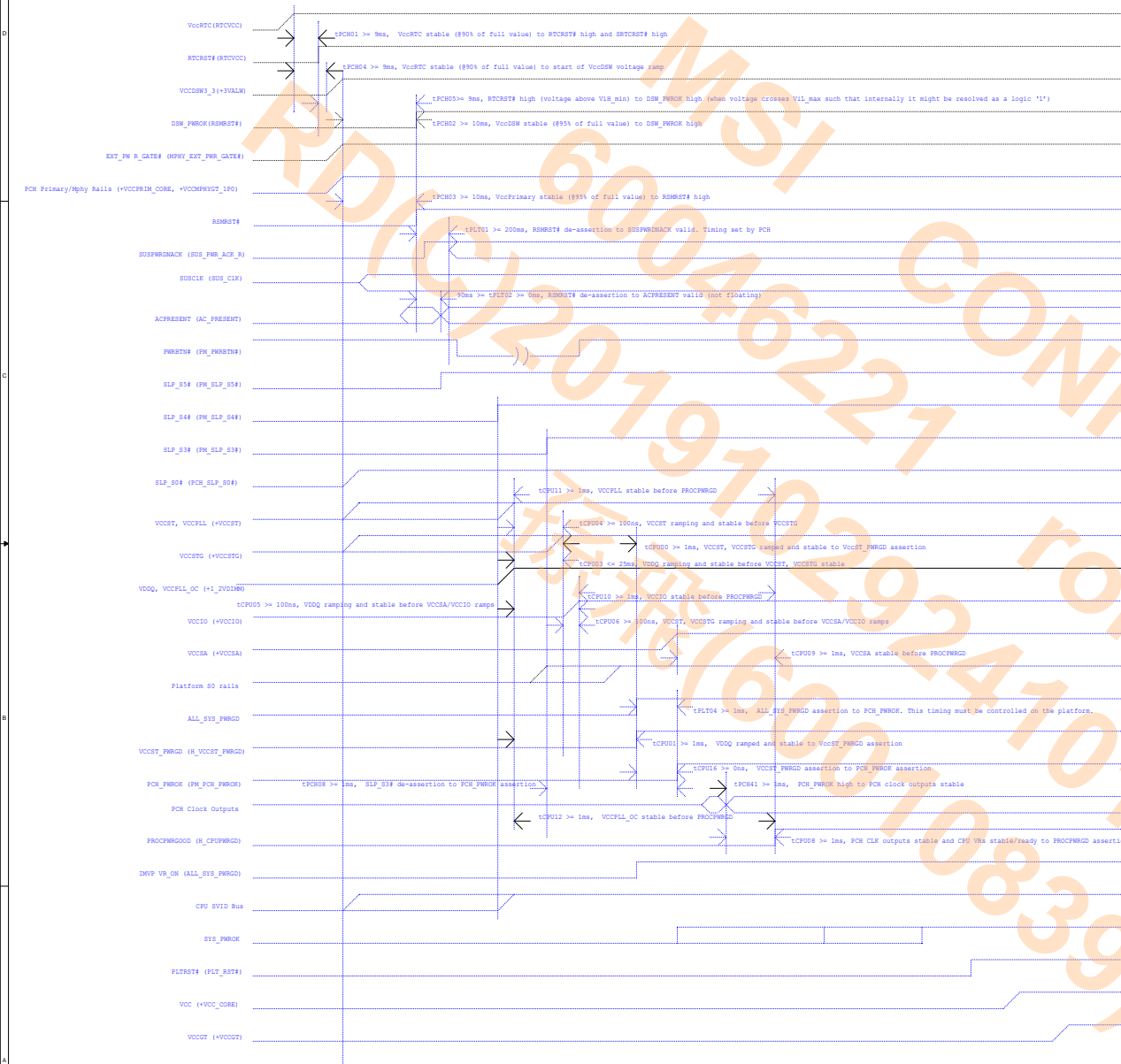




13H1 Power Delivery Chart

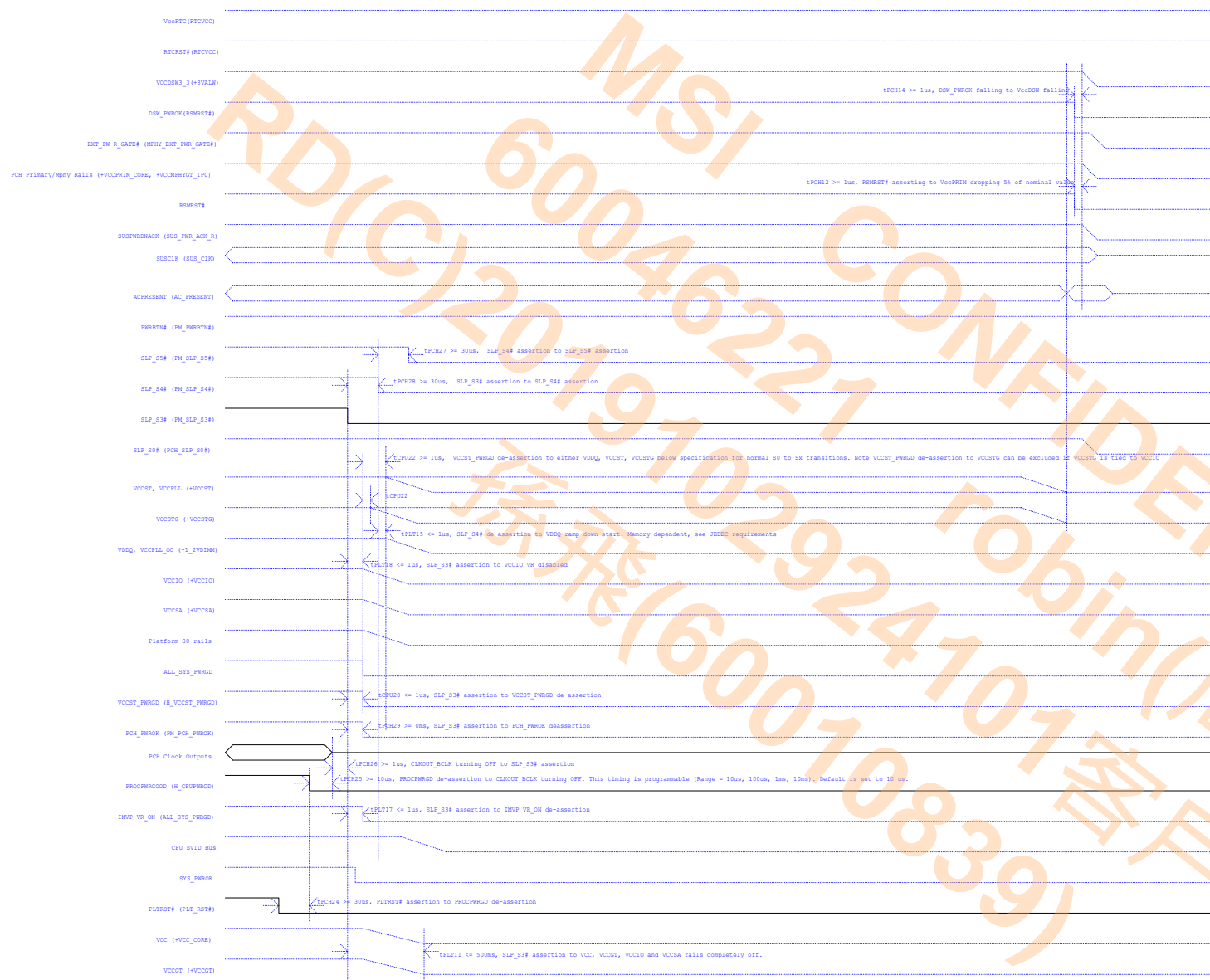


G3 to S0



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S0 to G3



- 497: 2018/11/02 Page18 Add R485 for TP525810 overcurrent heat issue
- 498: 2018/11/02 Page18 Add Type-C_OCR of signal for TP525810 overcurrent heat issue (Shut TP5NC173)
- 499: 2018/11/02 Page11 Change signal from USB_OC# to Type-C_OC# for TP525810 overcurrent heat issue
- 500: 2018/11/06 Page18 Update PCB shielding symbol by manufacturing suggest
- 501: 2018/11/06 Page11 Un-stuff R213 because IC control pin is push-out by NEC request
- 502: 2018/11/13 Page18 Change C261 from 220uf to 470uf for SA request
- 503: 2018/11/13 Page11 Change R373 R374 from 0 ohm to 100 ohm by NEC request
- 504: 2018/11/16 Page22 Change F2011 F2012 from AC20802 to AC20806 for USB3.0 bus break by NEC request
- 505: 2018/11/16 Page25 Det F2014 F2016 and add ED109 ED110 ED111 ED112 From ES08040 to F208015M for PS-component add by NEC request
- 506: 2018/11/16 Page18 Change R433 from 100 ohm to 500 ohm by NEC request
- 507: 2018/11/16 Page25 Change R422 from 243 ohm to 390 ohm by NEC request
- 508: 2018/11/19 Page20 Remove L1M633 by ME request
- 509: 2018/11/19 Page24 Change R37 value from 2.2kOhm to 10kOhm for ME cannot be detected
- 510: 2018/11/22 Page18 Det RTC crystal 2nd source, Remove RTC crystal virtual component(196)
- 511: 2018/11/22 Page18 Add virtual component for JSM crystal by different ROM(17)
- 512: 2018/11/22 Page17 Shift EC15,EC16,EC18,EC19 by EM suggest
- 513: 2018/11/27 Page27 Change C418 from 100uf to 220uf for voltage drop of +3V_LTE
- 514: 2018/11/29 Page18 Change ME voltage(L1M630) main source from 50V-50V12V1_040 to 50V 50V12V1_042 by ME request
- 515: 2018/11/29 Page24 Change T10A1002A setting by vendor suggest(CH2_C02_C02_002 from 1.0 to R4) Un-stuff R225, Un-stuff R231, Change R232 from 1K ohm to 20K ohm
- 516: 2018/11/29 Page18 Add WiFi Module Mxler by ME request (L1M630)
- 517: 2018/11/29 Page25 Add Power Adapter Type 2 by ME request (L1M631)
- 518: 2018/11/29 Page18 Add Power Adapter Type 2 by ME request (L1M631)
- 519: 2018/11/29 Page18 Add Rubber (Square) by ME request (L1M631)
- 520: 2018/11/29 Page18 Add Rubber (Square) by ME request (L1M631)
- 521: 2018/11/29 Page18 Add Rubber (Circle) by ME request (L1M631)
- 522: 2018/11/29 Page18 Add SMA Connector Mxler by ME request (L1M630)
- 523: 2018/11/29 Page18 Change PCB 97% from PDS-1301120-H73 to PDS-1301120-H73 97CB2
- 524: 2018/11/19 Page23 Un-stuff R515 for Type-C USB3.1 GEN2 compliance test by NEC request
- 525: 2018/11/16 Page23 Change R325 R323 from 20K ohm to 1K ohm for Type-A compliance test by NEC request
- 526: 2018/11/16 Page23 Un-stuff R328 R328 for Type-A compliance test by NEC request
- 527: 2018/11/17 Page18 L1M670 and L1M671 change to Un-stuff by ME request
- 527: 2018/12/17 Page18 Add Thermal DCR Sponge for S063 by ME request (L1M671)

